



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



MPI40-V2

High current, low profile, miniature power inductors



Product features

- High current carrying capacity
- Magnetically shielded, Low EMI
- Rugged flexible construction
- Self resonant frequency (SRF) greater than 9.5 MHz
- Inductance range from 0.1 μ H to 22 μ H
- Current range from 1.2 A to 22 A
- 4.75 mm x 4.45 mm footprint surface mount package in 1.2 mm, 1.5 mm, and 2.0 mm heights
- Moisture Sensitivity Level (MSL): 1

Applications

- Handheld/mobile devices
- Portable media players
- Notebook/netbook/laptop regulators
- Tablets/smartbooks
- Battery operated devices
- LED drivers
- LCD displays
- Point-of-load (POL) converters

Environmental data

- Storage temperature range (Component): -55 °C to +125 °C
- Operating temperature range: -55 °C to +125 °C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020 (latest revision) compliant
- Halogen free, lead free, RoHS compliant



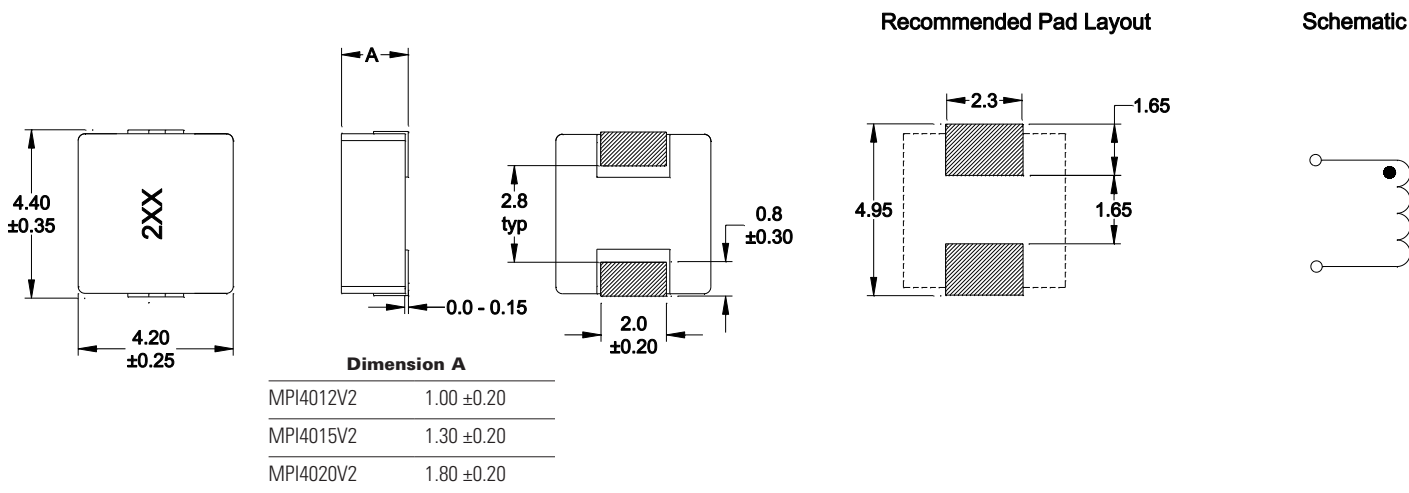
Product specifications

Part Number ⁵	OCL ¹ (μ H) \pm 20%	Part marking designator	I_{rms}^2 (A)	I_{sat}^3 (A)	DCR (m Ω) typical @ +20 °C	DCR (m Ω) maximum @ +20 °C	SRF (MHz) typical	K-factor ⁴
1.2 mm height								
MPI4012V2-R33-R	0.33	A	7.5	11	11	13.5	128	2480
MPI4012V2-R47-R	0.47	B	5.6	6.8	19	23	106	2470
MPI4012V2-R68-R	0.68	C	4.5	6.7	28	33.5	98	2223
MPI4012V2-1R0-R	1.0	D	4.3	6.5	38.5	46.5	64	1477
MPI4012V2-1R5-R	1.5	E	3.3	4.3	55	66	63	1264
MPI4012V2-2R2-R	2.2	F	2.9	4.2	75	90	35	1143
MPI4012V2-4R7-R	4.7	G	1.8	2.8	175	210	29	890
1.5 mm height								
MPI4015V2-R22-R	0.22	A	10.5	14	6.0	7.5	153	2649
MPI4015V2-R33-R	0.33	B	9.5	11	7.0	8.5	120	2158
MPI4015V2-R47-R	0.47	C	7.8	9.0	11	14	98	1991
MPI4015V2-R56-R	0.56	D	7.5	8.3	12	14	84	1942
MPI4015V2-R68-R	0.68	E	6.8	8.0	16	19	81	1437
MPI4015V2-1R0-R	1.0	F	5.5	6.0	23	27	56	1382
MPI4015V2-1R5-R	1.5	G	4.2	4.6	48	58	48	1468
MPI4015V2-2R2-R	2.2	H	2.9	4.5	65	78	42	920
MPI4015V2-3R3-R	3.3	I	3.0	3.2	77	92	31	854
MPI4015V2-4R7-R	4.7	J	2.2	3.0	108	130	22	791
MPI4015V2-6R8-R	6.8	K	2.0	2.3	172	207	21	609
MPI4015V2-100-R	10	L	1.8	2.1	245	294	14	766
2.0 mm height								
MPI4020V2-R10-R	0.10	A	16	22	3.5	4.5	343	2692
MPI4020V2-R22-R	0.22	B	13	17	5.5	6.6	165	2036
MPI4020V2-R33-R	0.33	C	9.5	12	7.5	9.0	113	1268
MPI4020V2-R47-R	0.47	D	8.5	11	10.5	13	95	1219
MPI4020V2-R56-R	0.56	E	8.0	10	12	15	87	1205
MPI4020V2-R68-R	0.68	F	7.5	9.0	12.5	16	80	1201
MPI4020V2-1R0-R	1.0	G	6.5	7.0	20	24	65	1168
MPI4020V2-1R2-R	1.2	H	6.5	6.8	23	28	52	1110
MPI4020V2-1R5-R	1.5	I	5.0	6.0	25	30	45	1038
MPI4020V2-2R2-R	2.2	J	3.8	5.5	40	48	33	711
MPI4020V2-3R3-R	3.3	K	3.3	4.0	71	85	25	643
MPI4020V2-4R7-R	4.7	L	2.7	3.2	98	118	24	453
MPI4020V2-6R8-R	6.8	M	2.0	2.6	167	192	23	482
MPI4020V2-100-R	10	N	1.7	2.2	245	281	17	307
MPI4020V2-150-R	15	O	1.5	1.8	320	384	13	257
MPI4020V2-220-R	22	P	1.2	1.65	350	402	9.5	215

1. Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 1.0 Vrms, 0.0 Adc, +25 °C.
 2. I_{rms} : DC current for an approximate temperature rise of 40 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +125 °C under worst case operating conditions verified in the end application.
 3. I_{sat} : Peak current for approximately 30% rolloff @ +25 °C.

4. K-factor: Used to determine Bp-p for core loss (see graph). $Bp-p = K * L * \Delta I$. Bp-p (Gauss), K: (K-factor from table), L: (Inductance in μ H), ΔI (Peak to peak ripple current in Amps).
 5. Part Number Definition: MPI40xxV2-xxx-R
 MPI40 = Product code
 xx= Height indicator
 V2=Version indicator
 xxx= inductance value in μ H, R= decimal point,
 If no R is present then last character equals number of zeros
 -R suffix = RoHS compliant

Dimensions (mm)



Part marking: 2xx (2 = version, x = inductance value per "Part marking designator" listed in Product specification table, x = bi-weekly date code)

All soldering surfaces to be coplanar within 0.10 millimeters

Tolerances are ± 0.3 millimeters unless stated otherwise

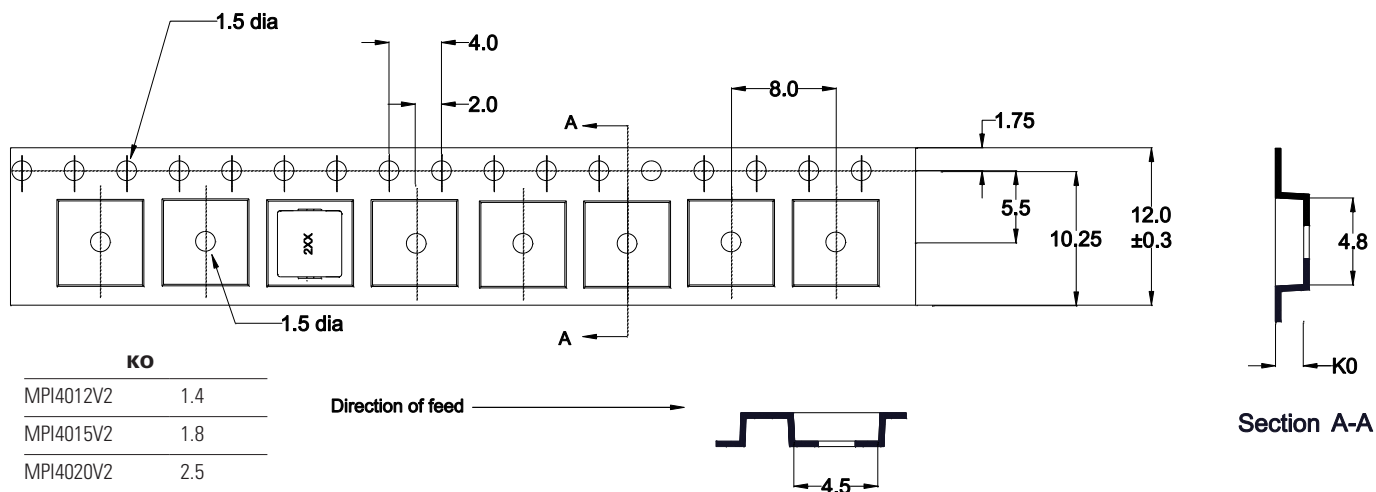
Pad layout tolerances are ± 0.1 millimeters unless stated otherwise

Do not route traces or vias underneath the inductor

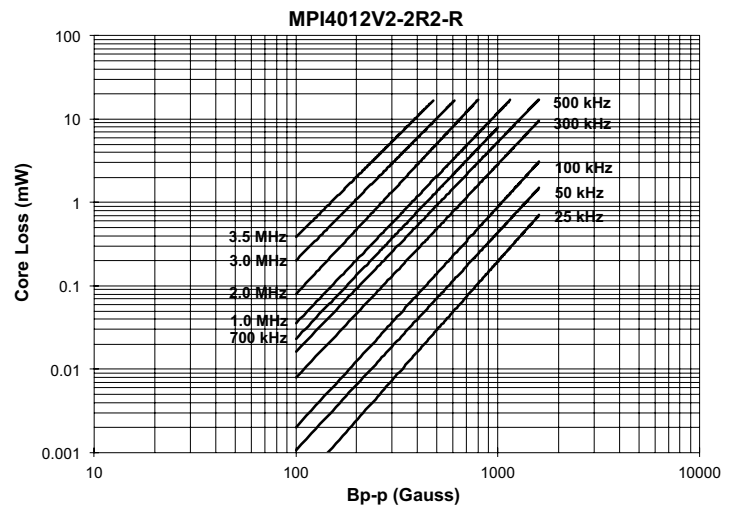
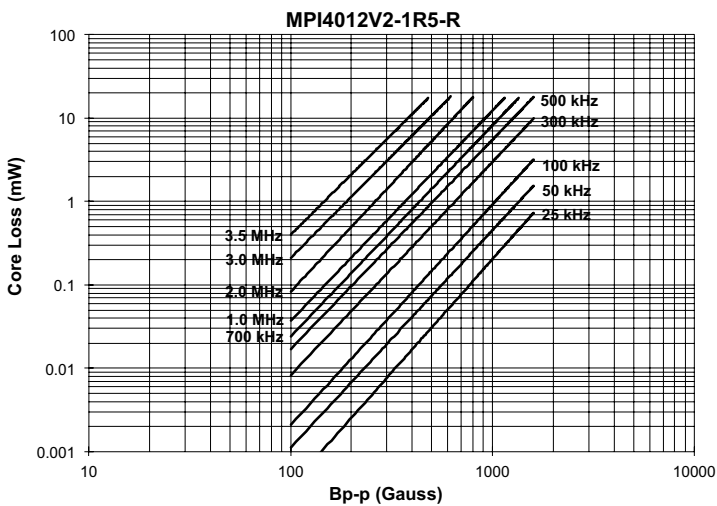
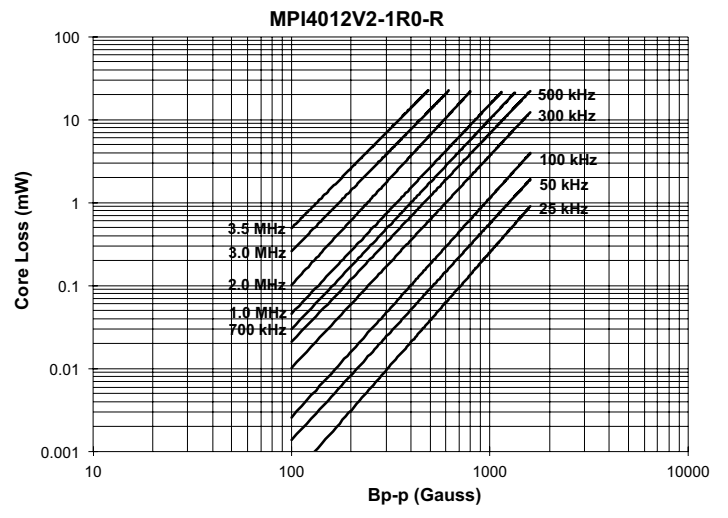
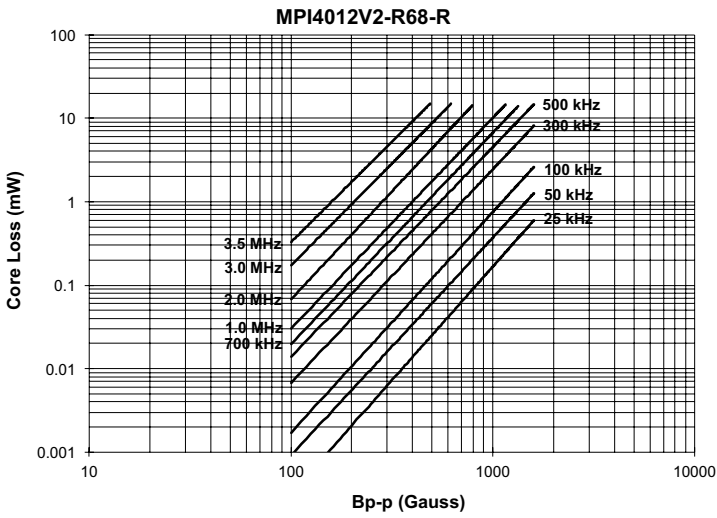
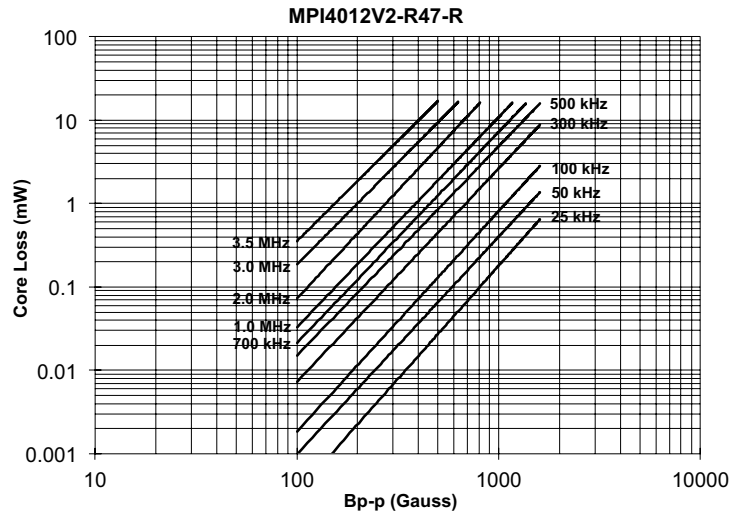
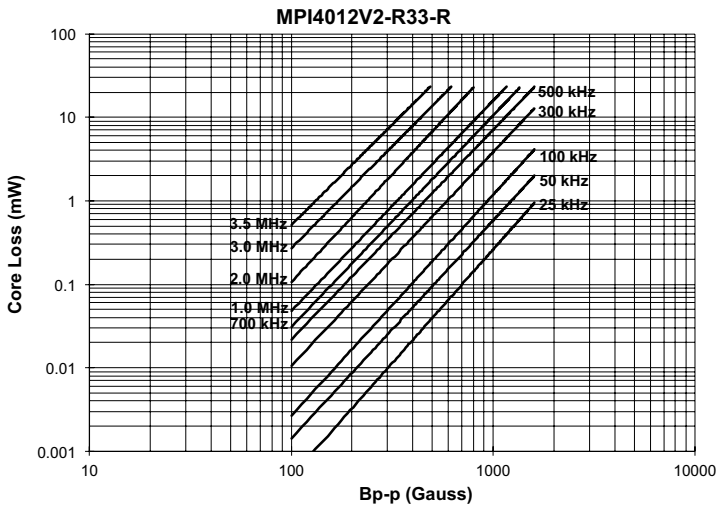
Packaging information (mm)

Drawing not to scale

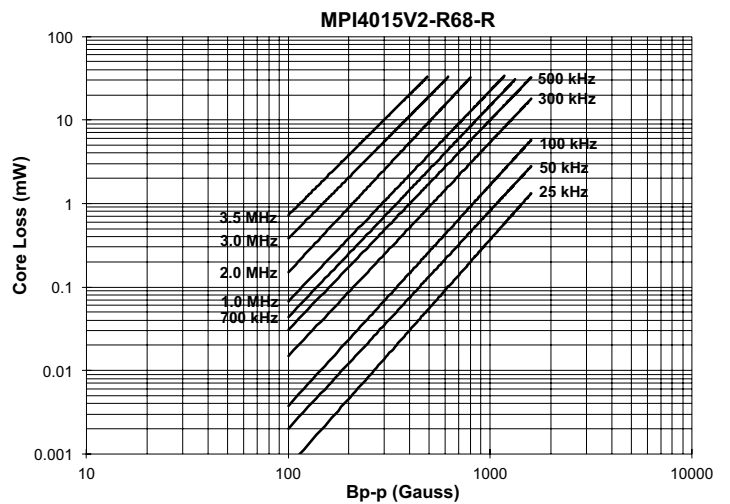
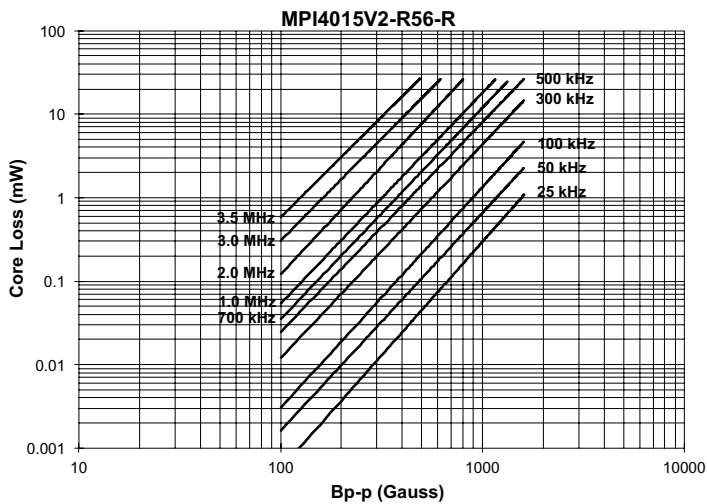
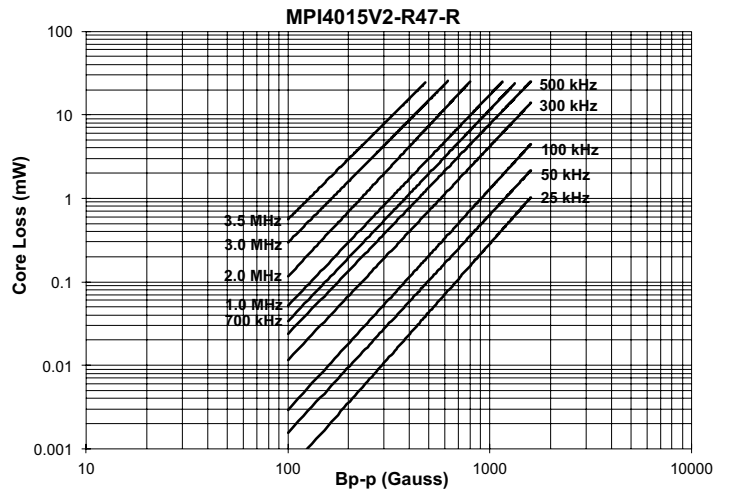
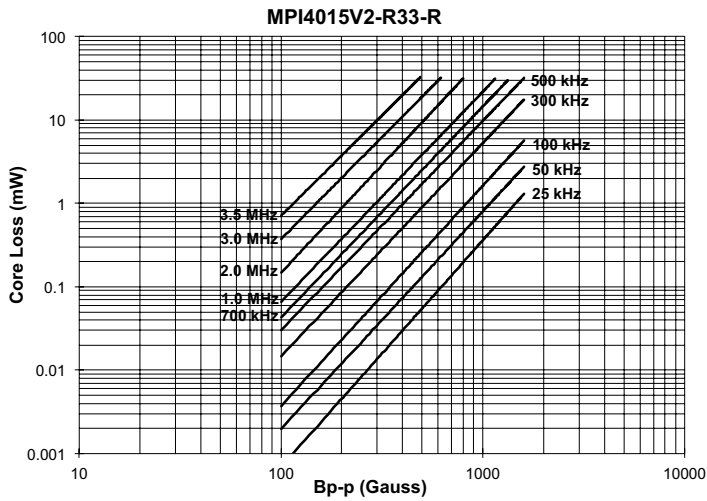
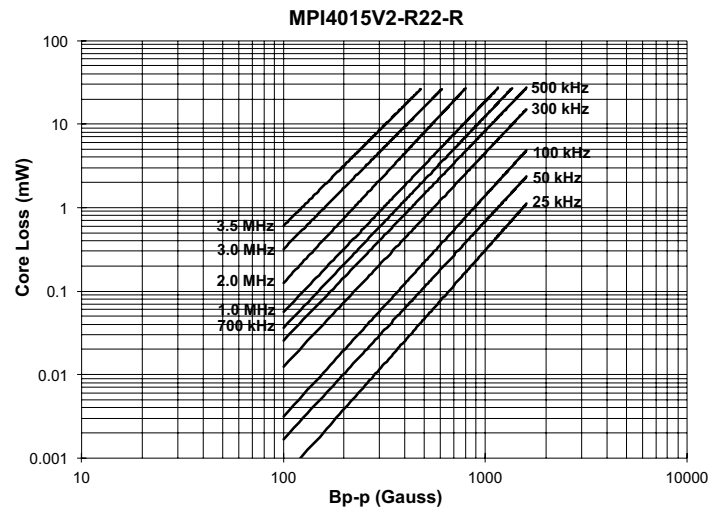
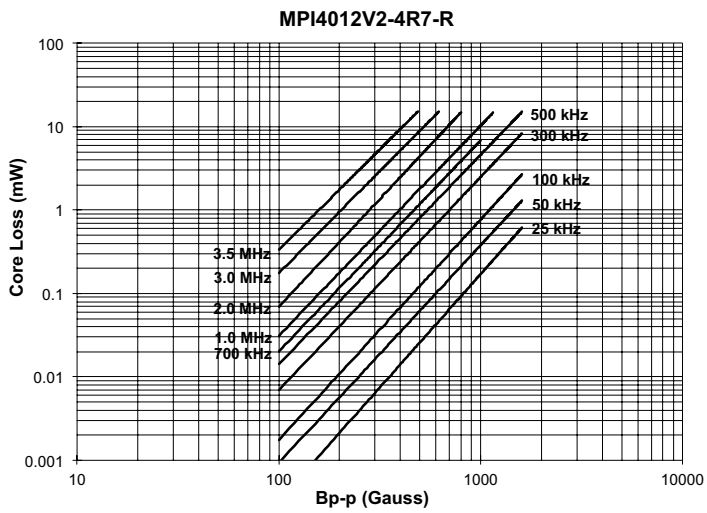
Supplied in tape and reel packaging, 3000 parts per 13" diameter reel



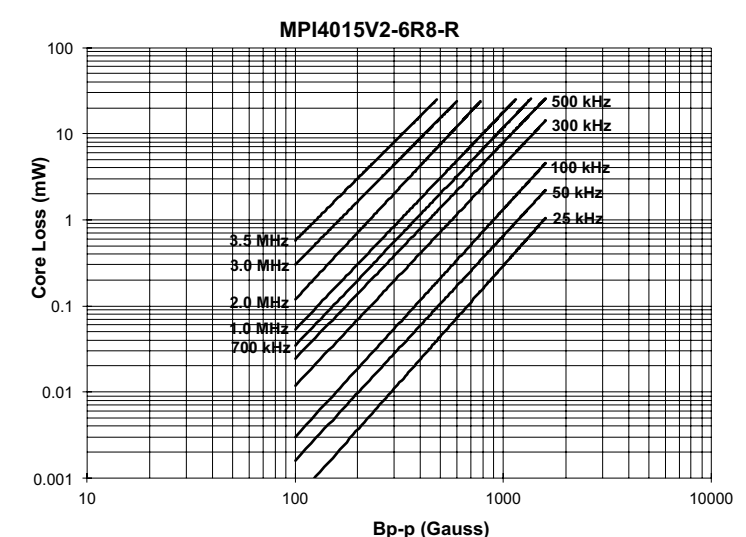
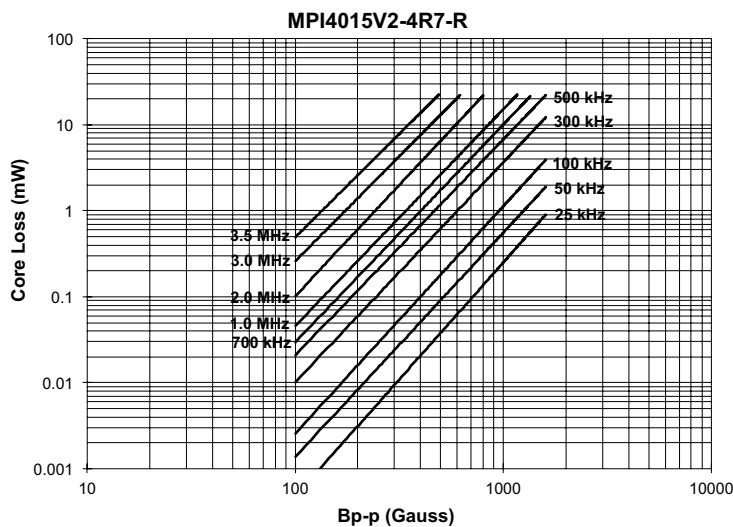
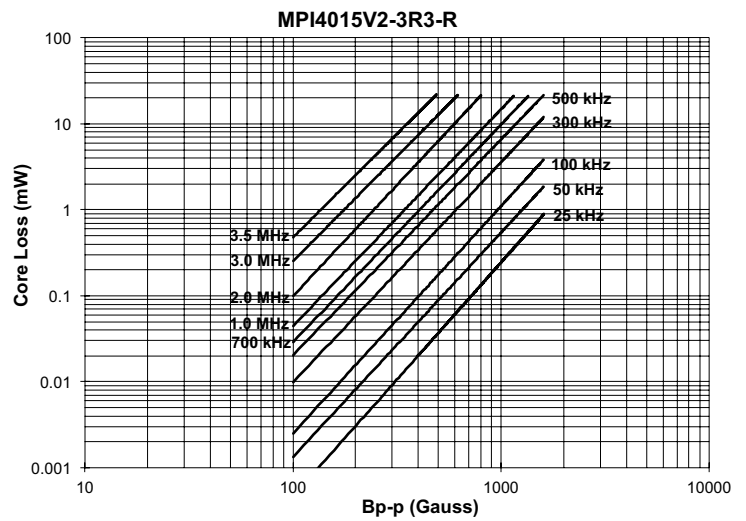
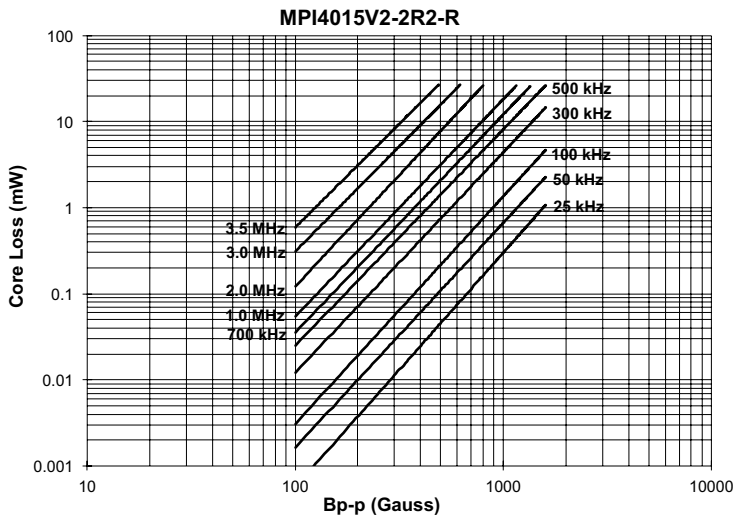
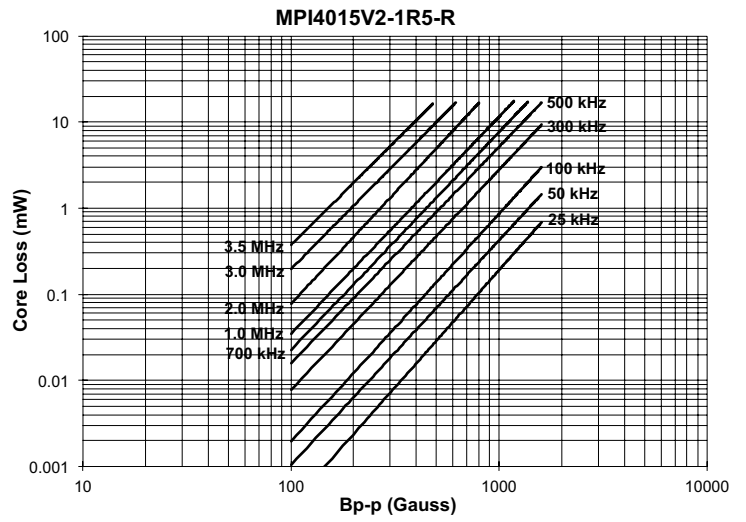
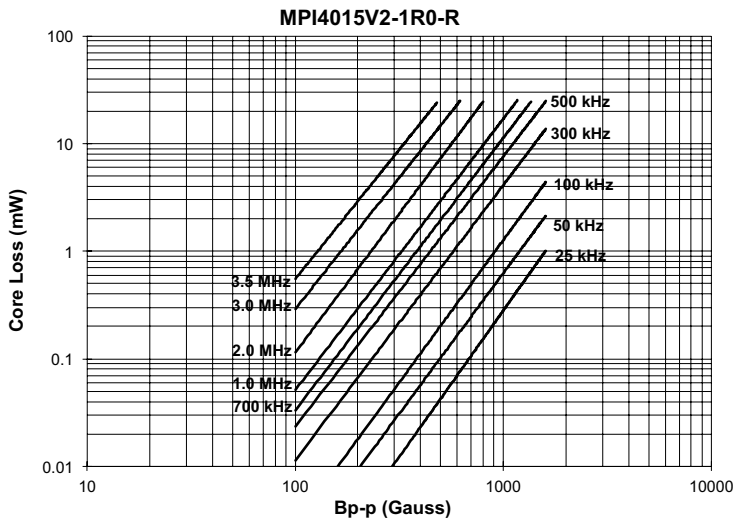
Core loss vs Bp-p



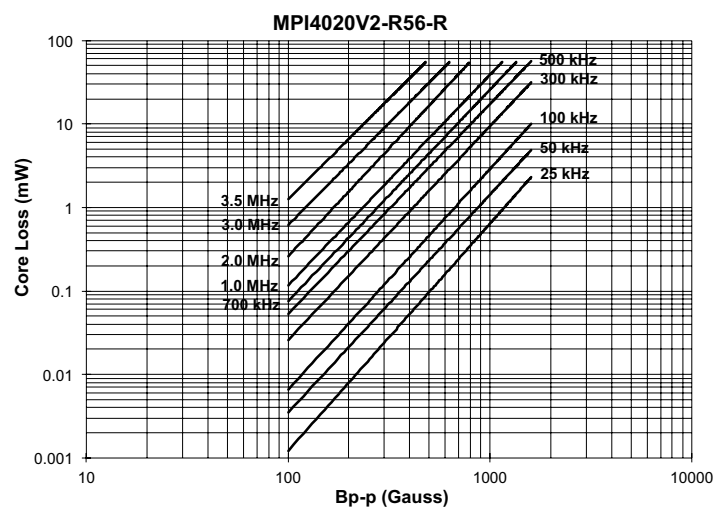
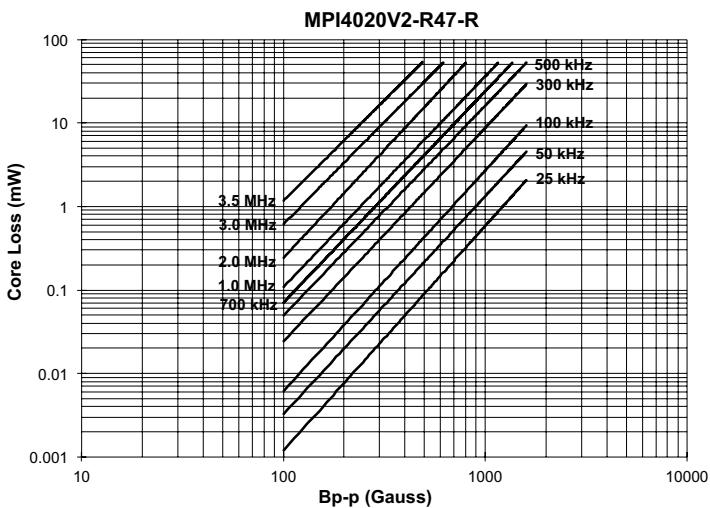
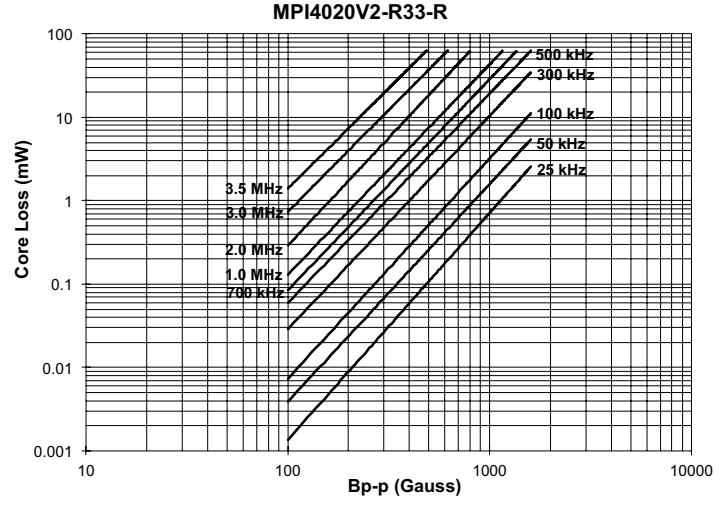
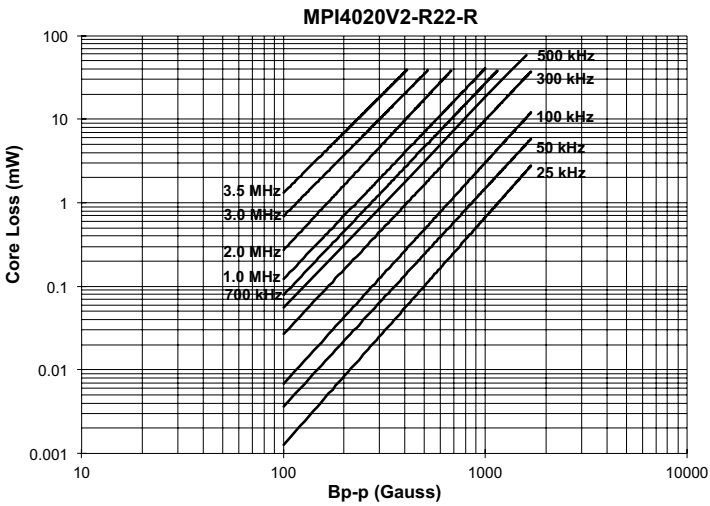
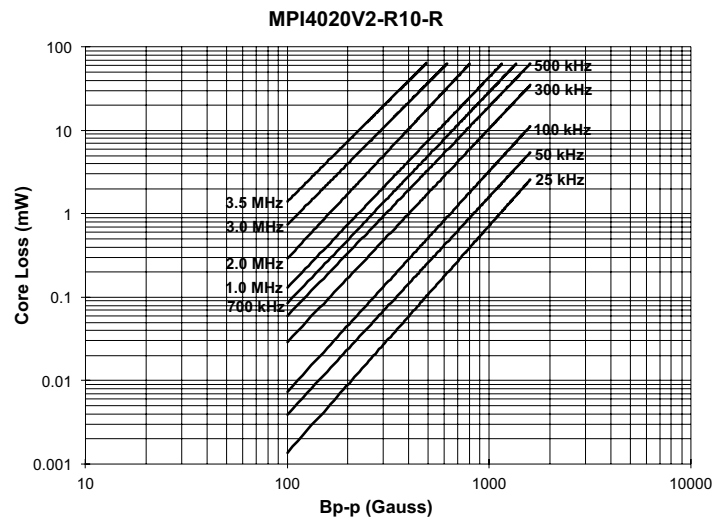
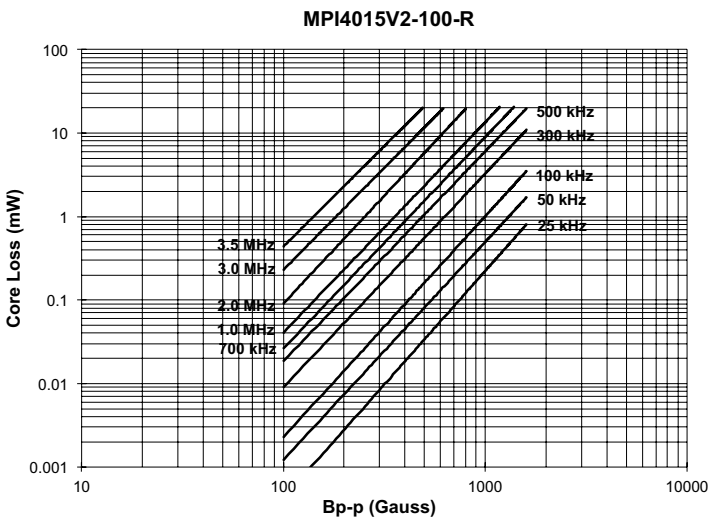
Core loss vs Bp-p



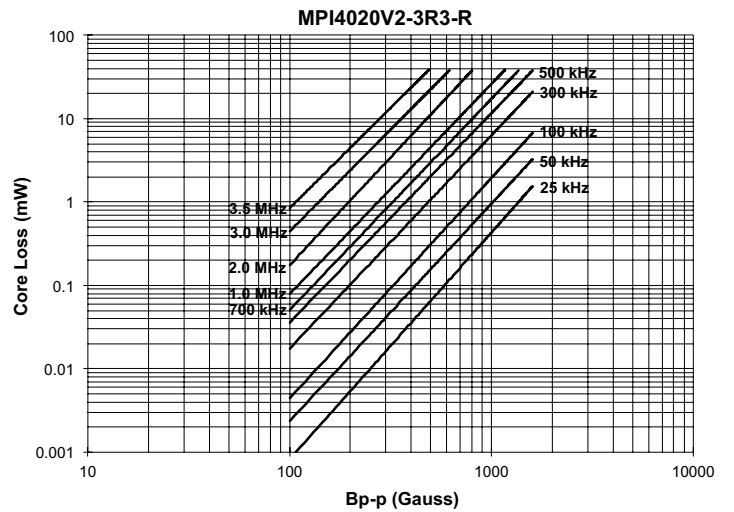
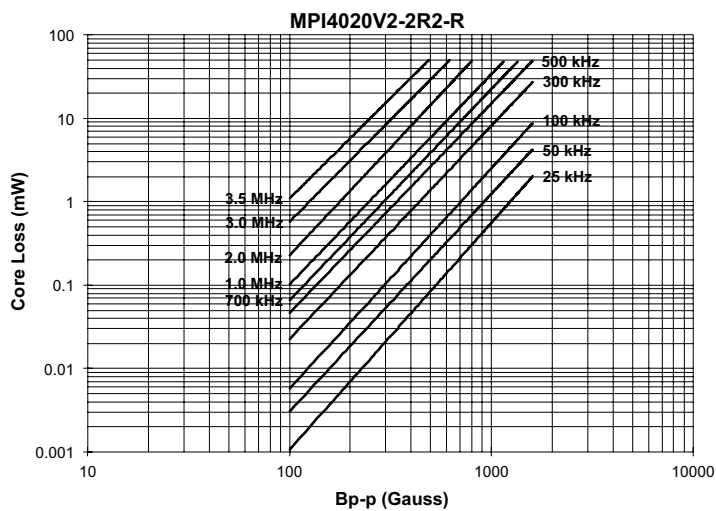
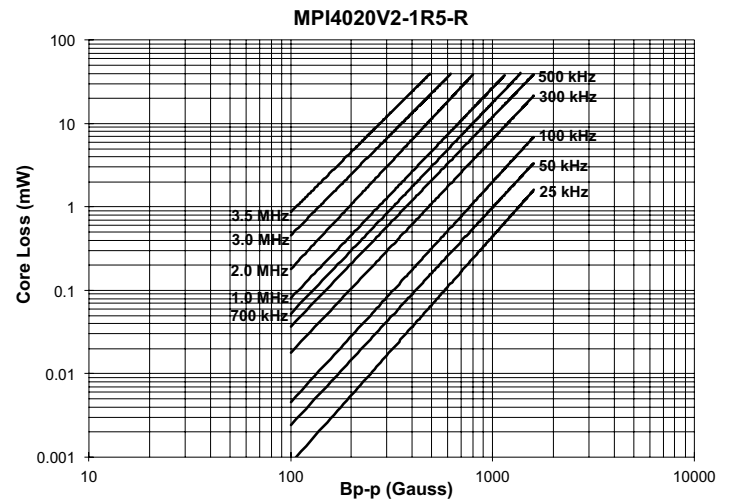
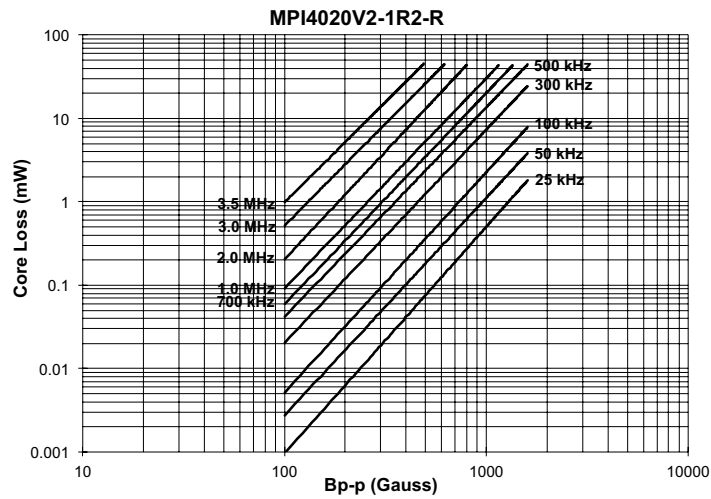
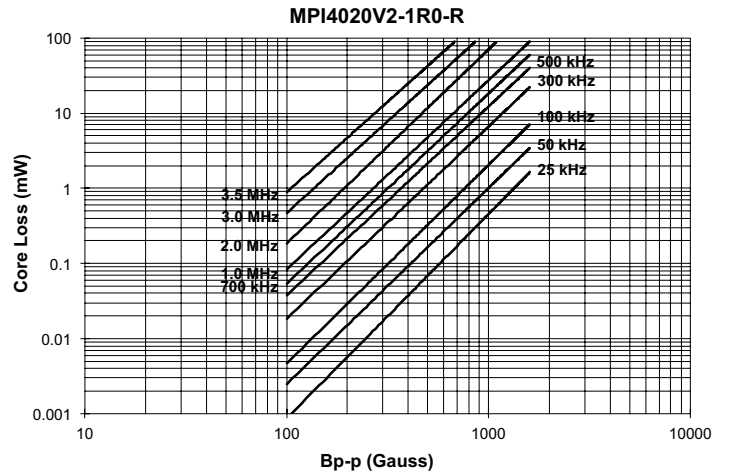
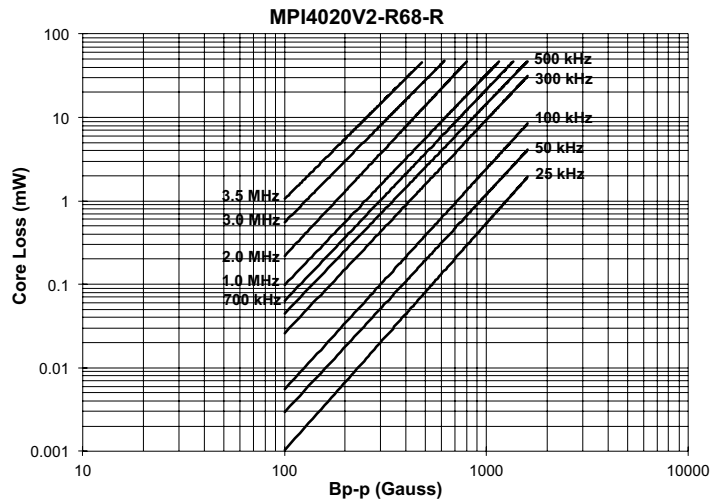
Core loss vs Bp-p



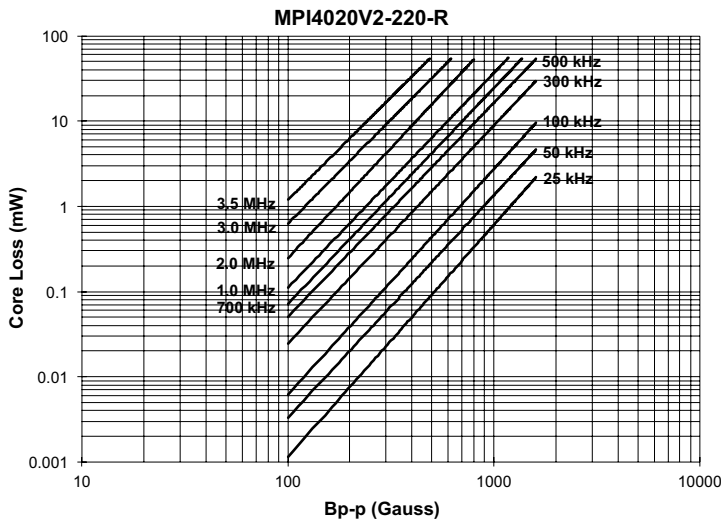
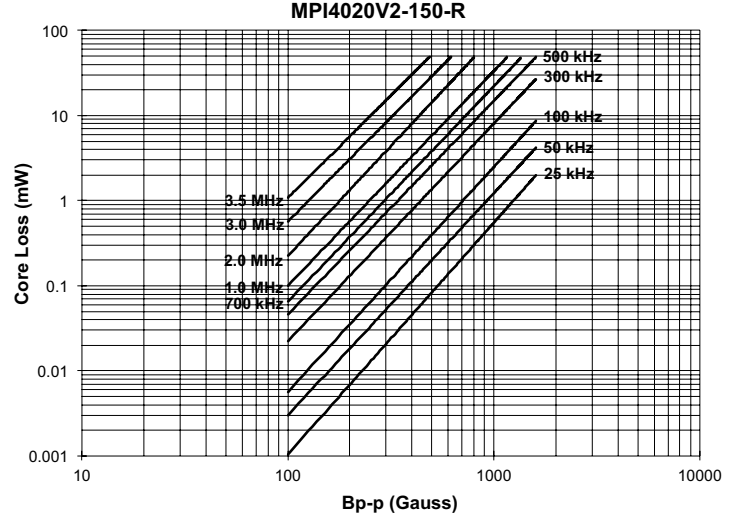
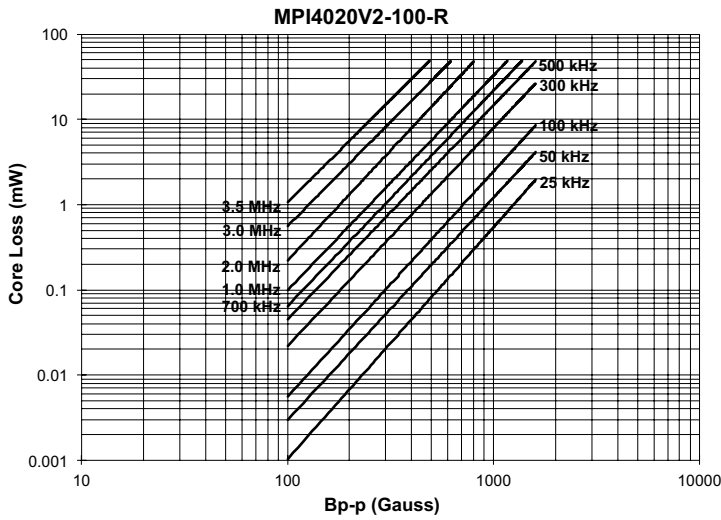
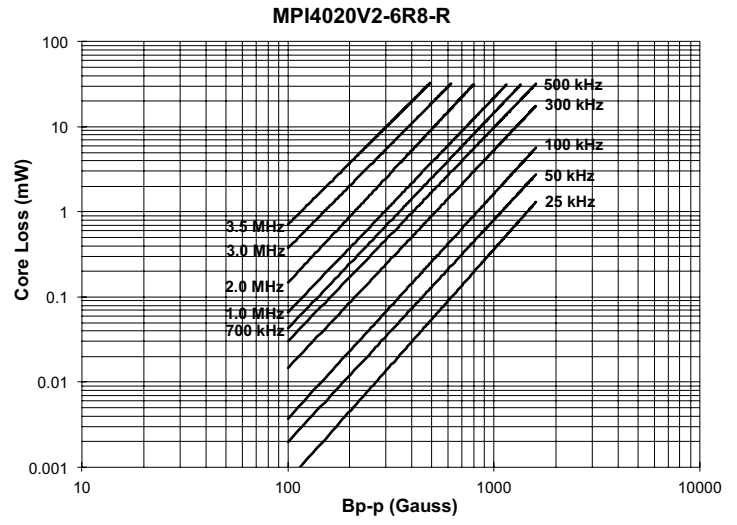
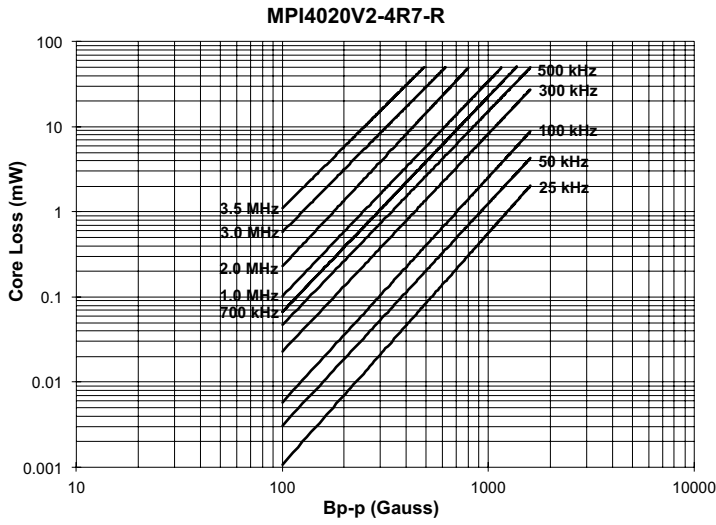
Core loss vs Bp-p



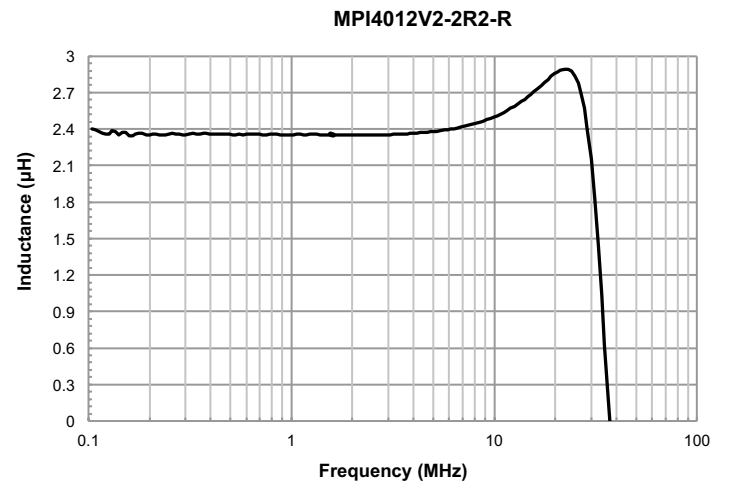
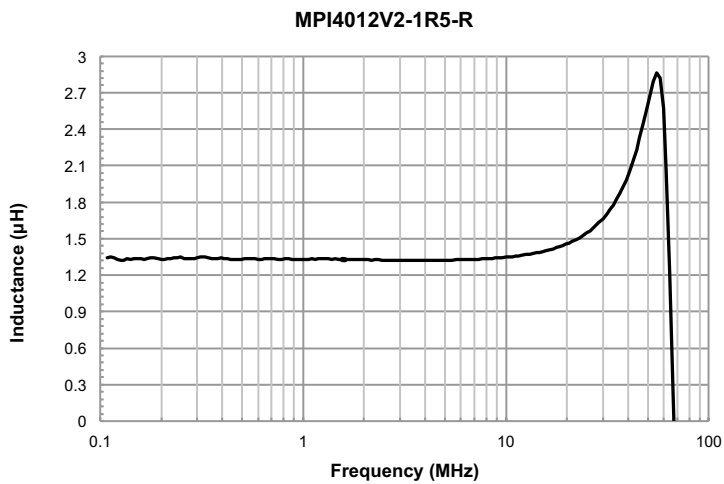
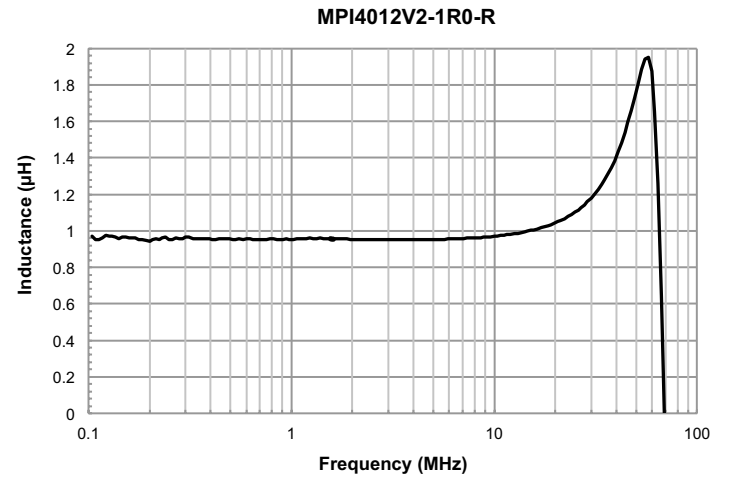
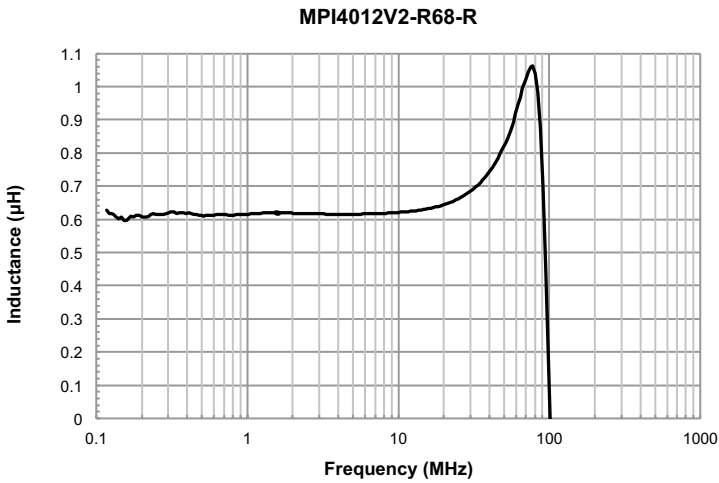
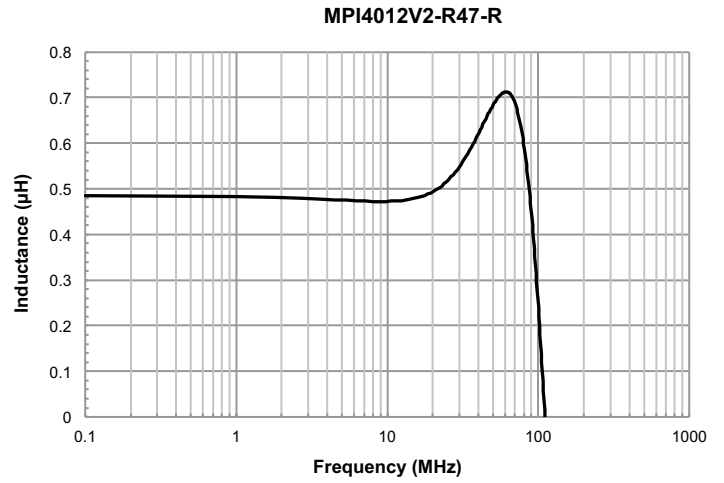
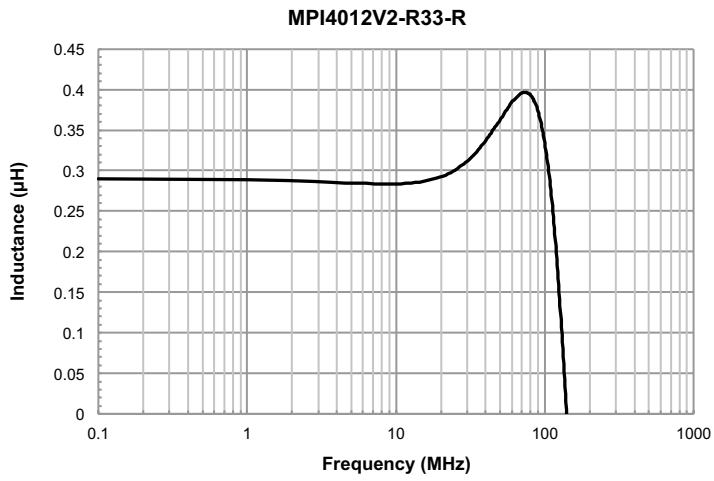
Core loss vs Bp-p



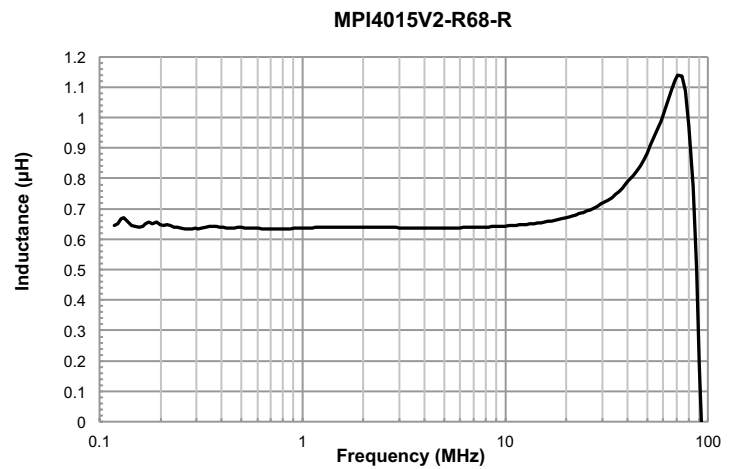
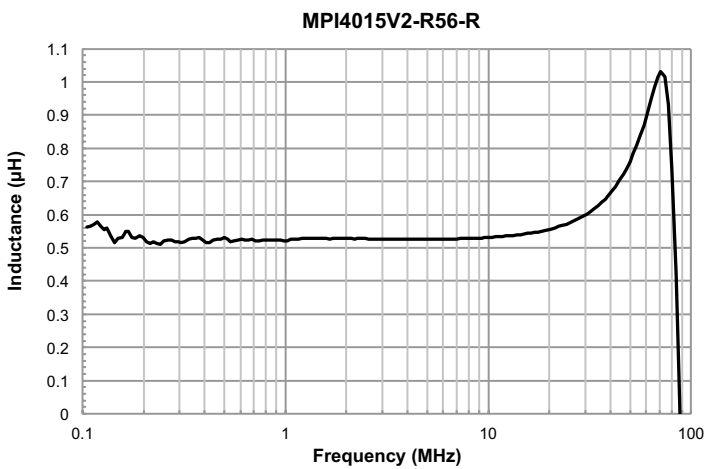
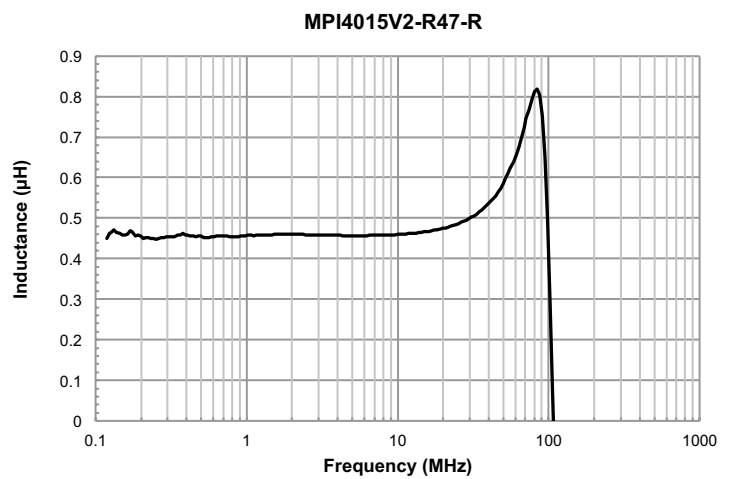
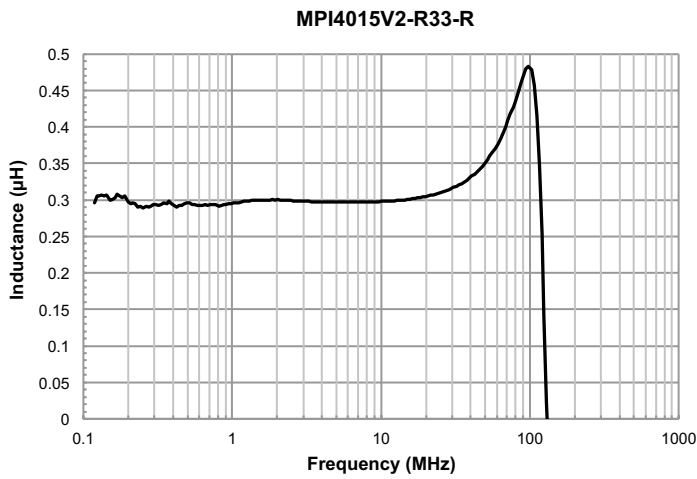
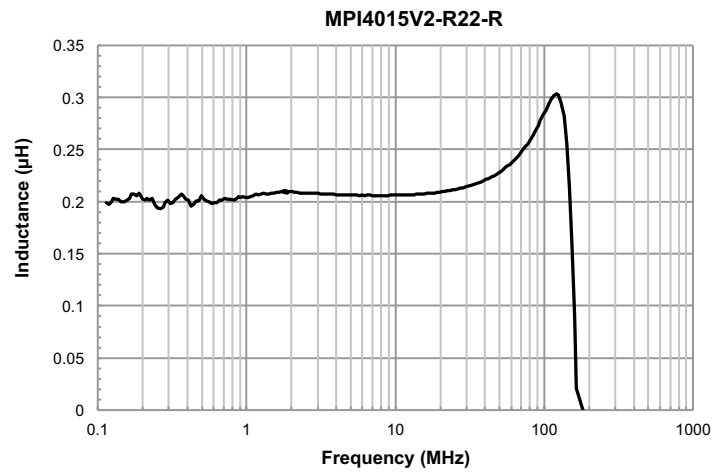
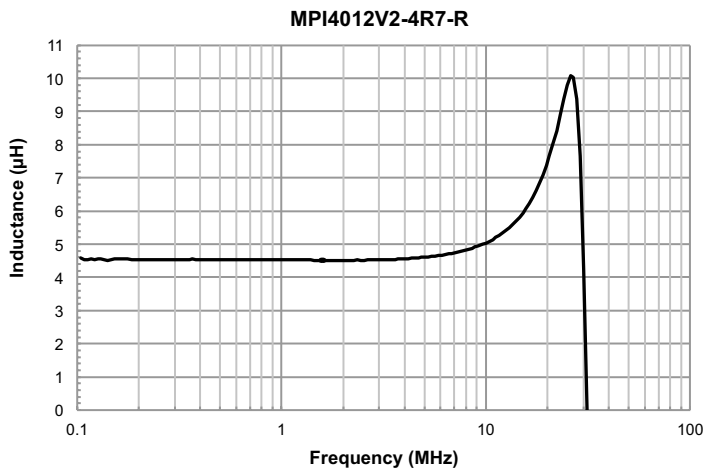
Core loss vs Bp-p



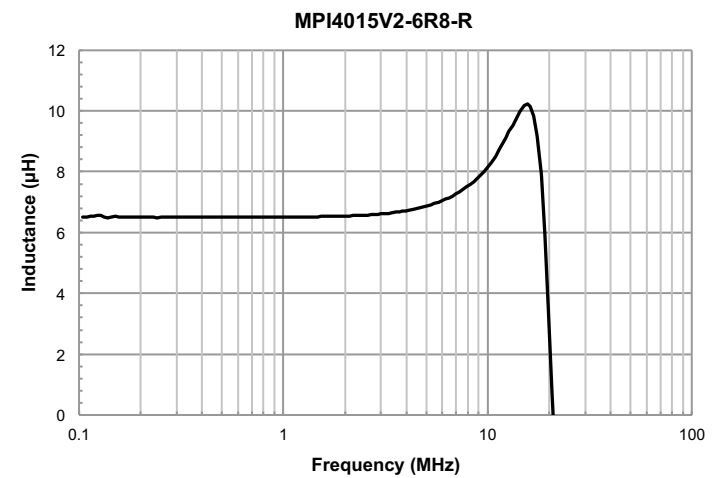
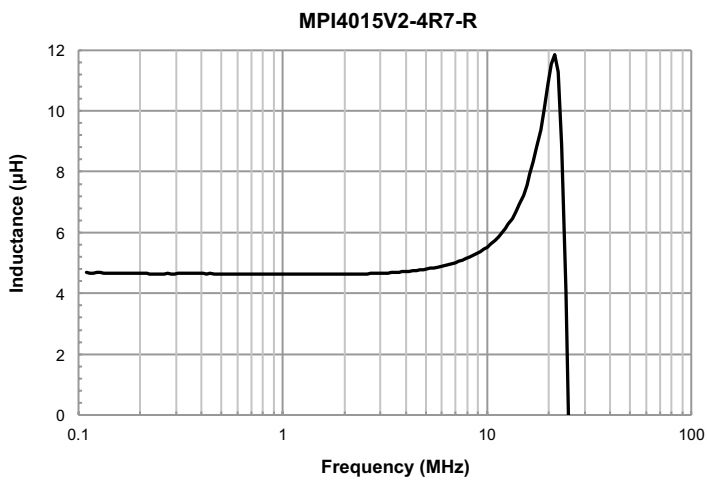
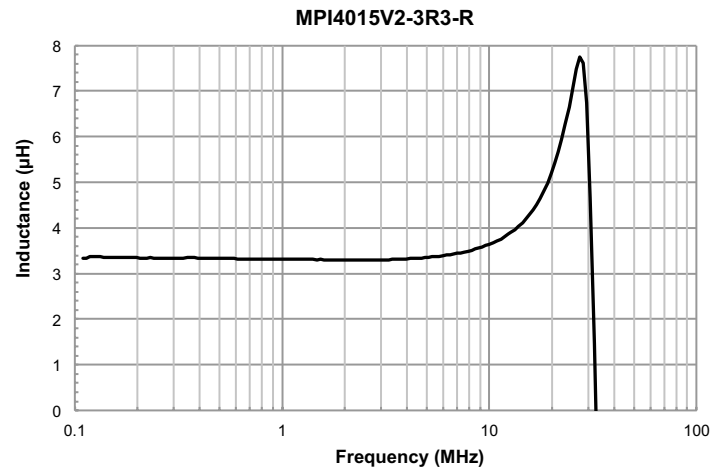
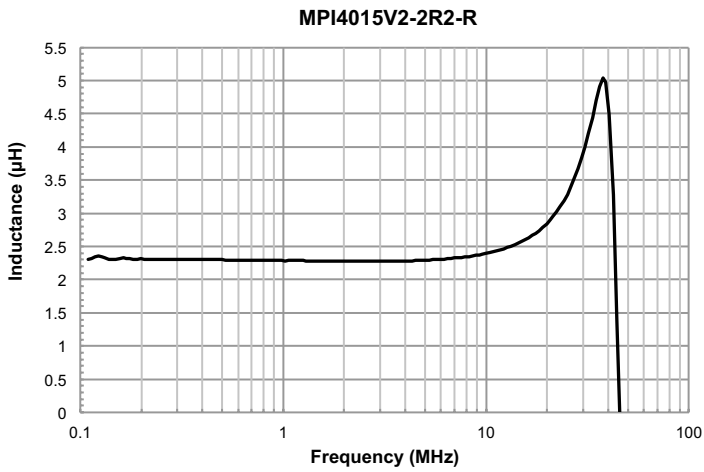
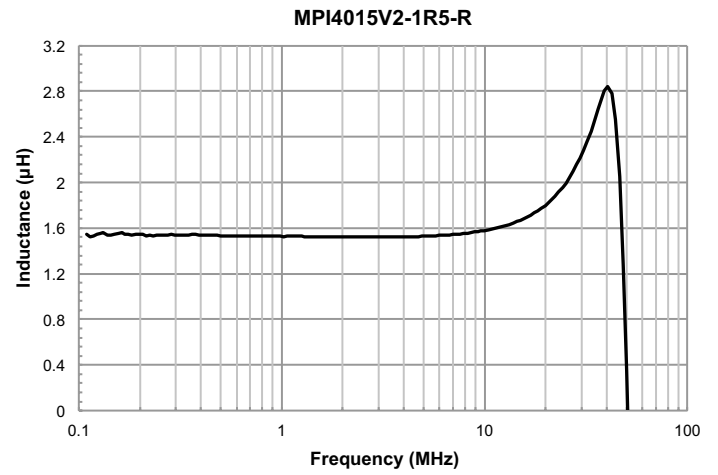
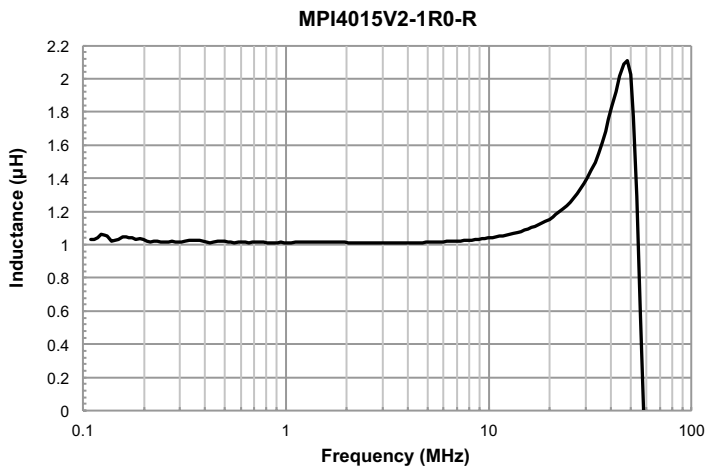
Inductance vs. Frequency



Inductance vs. Frequency

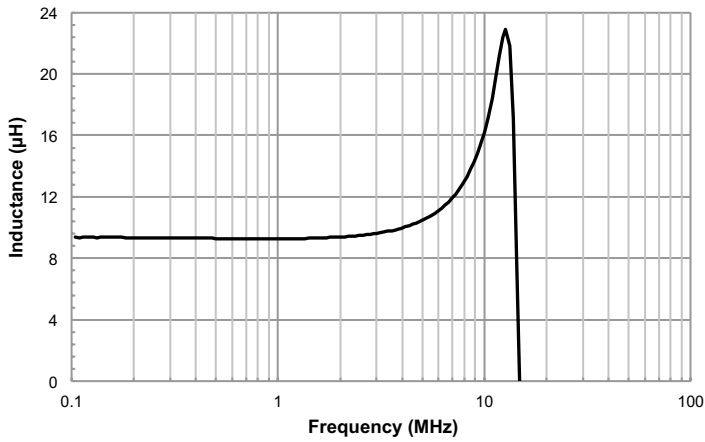


Inductance vs. Frequency

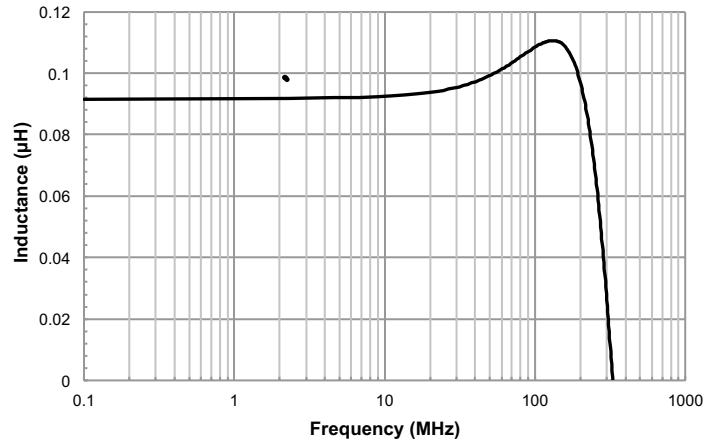


Inductance vs. Frequency

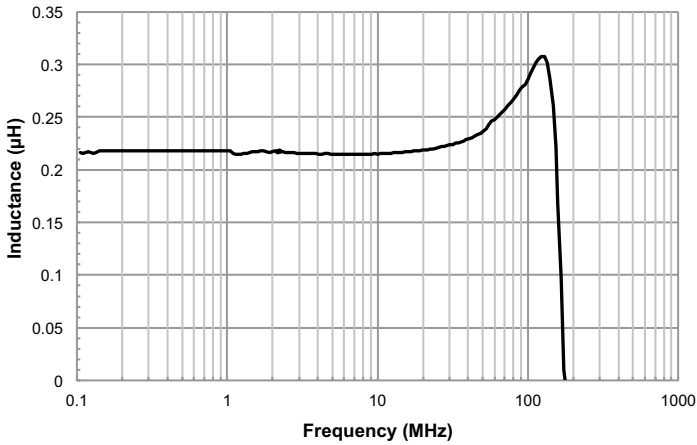
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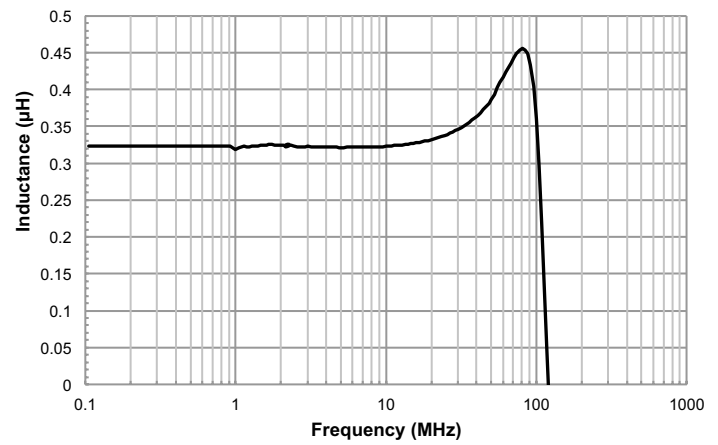
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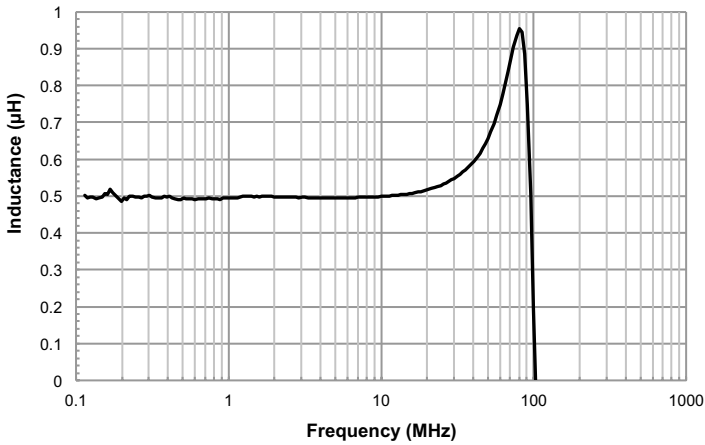
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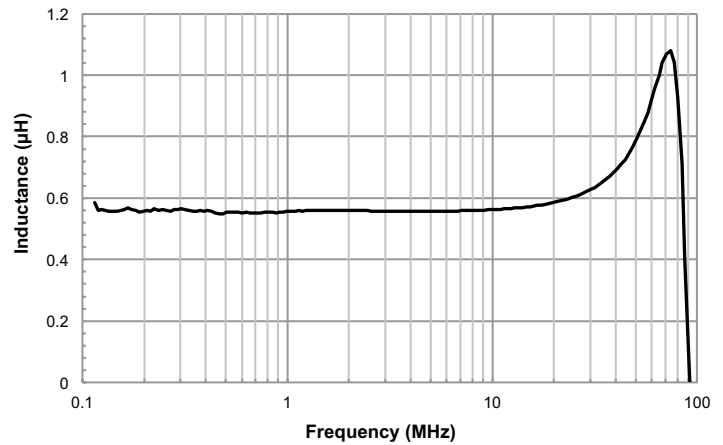
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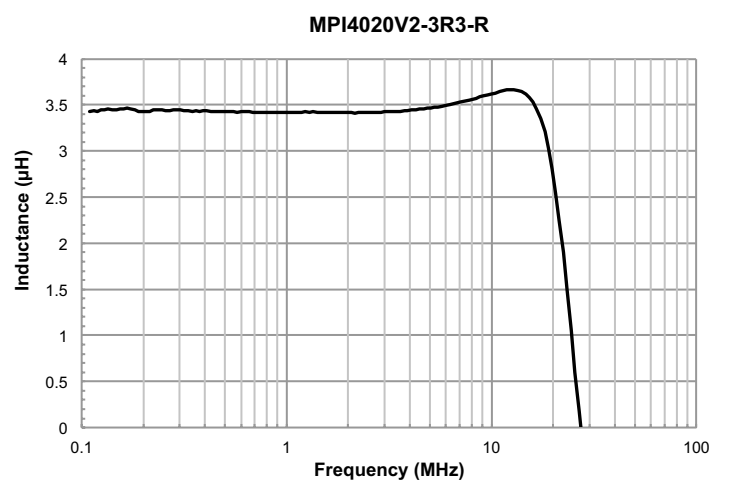
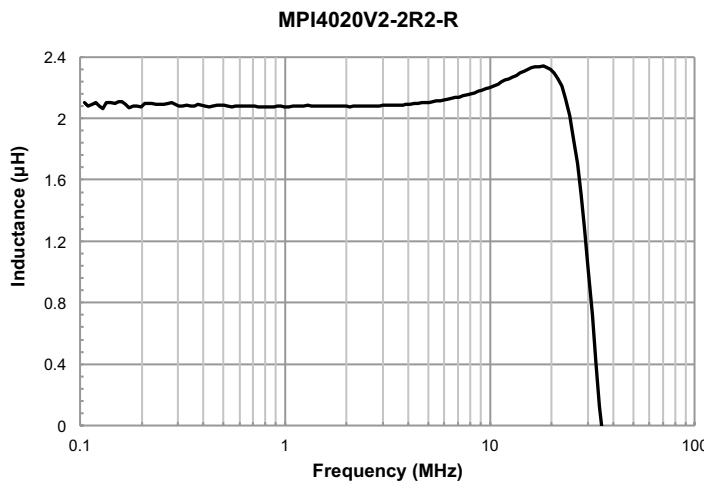
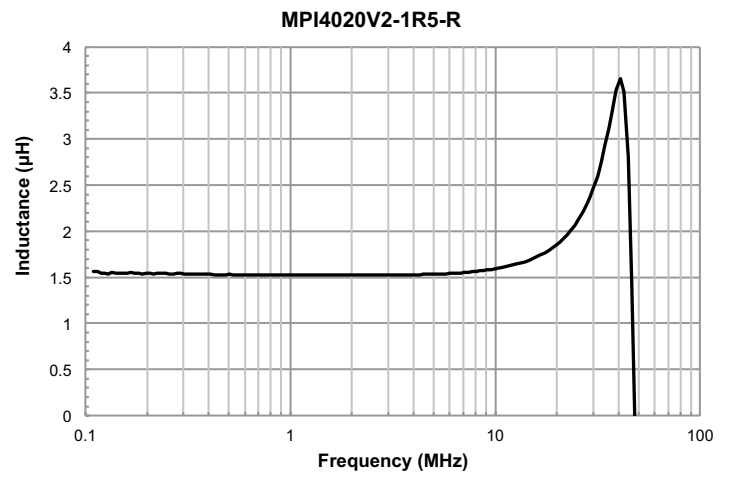
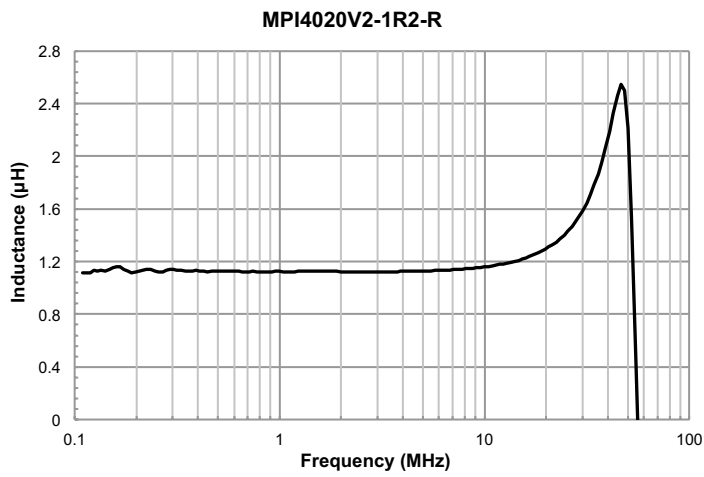
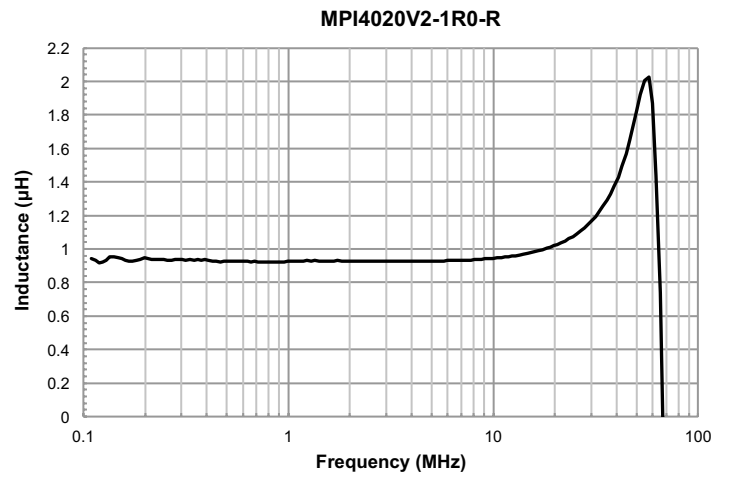
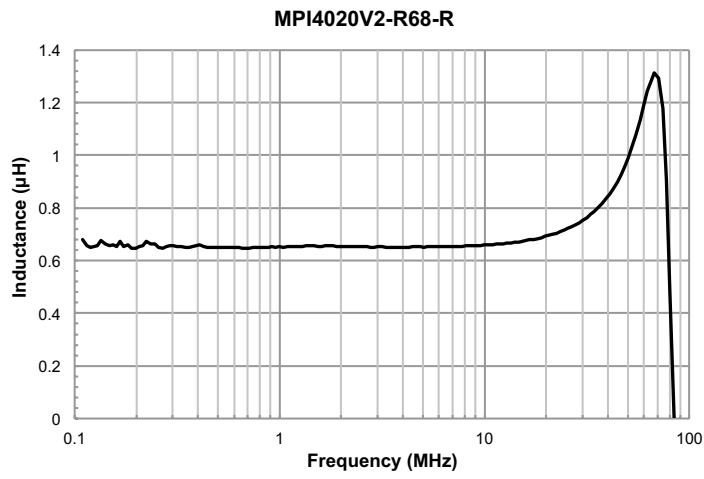
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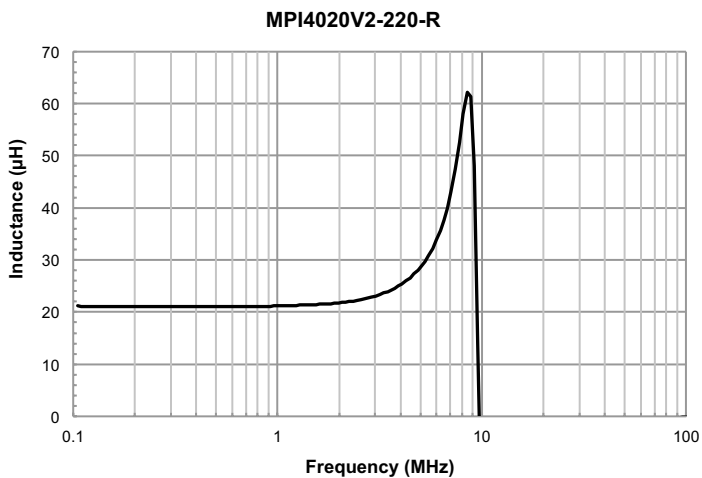
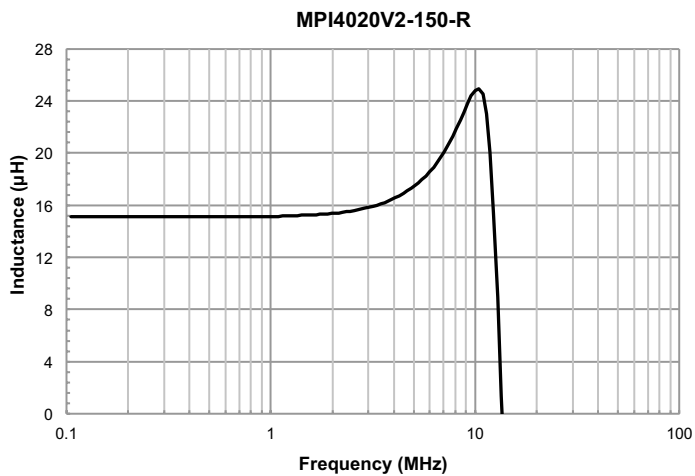
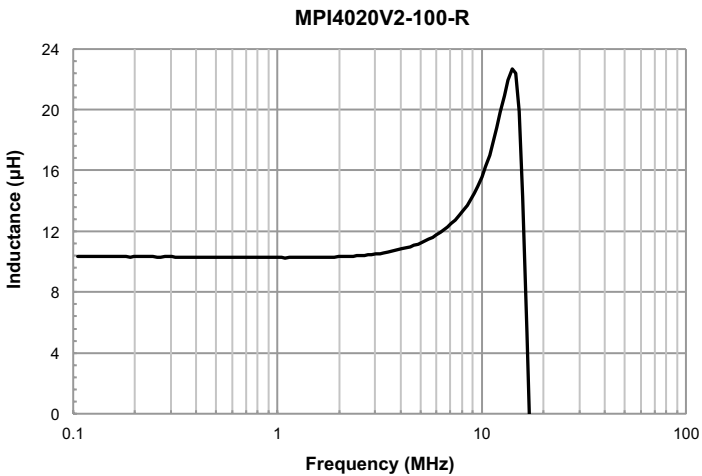
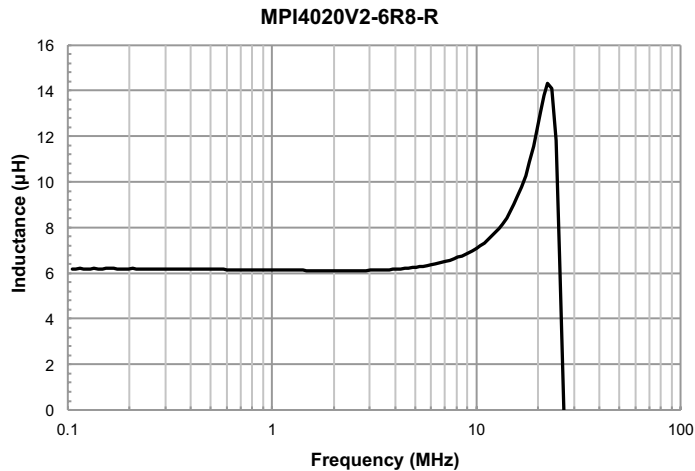
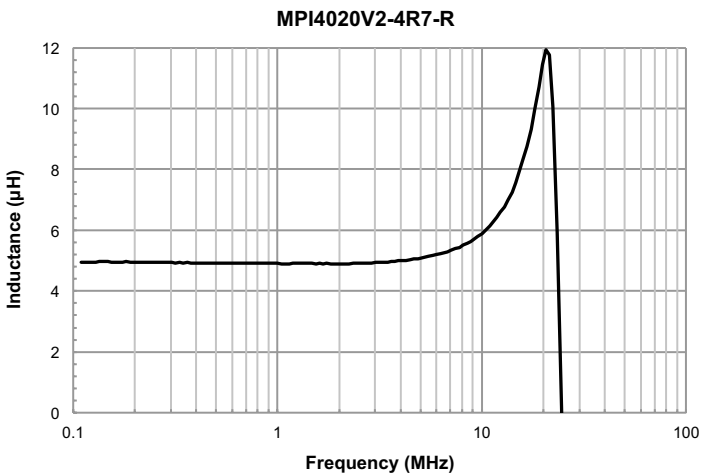
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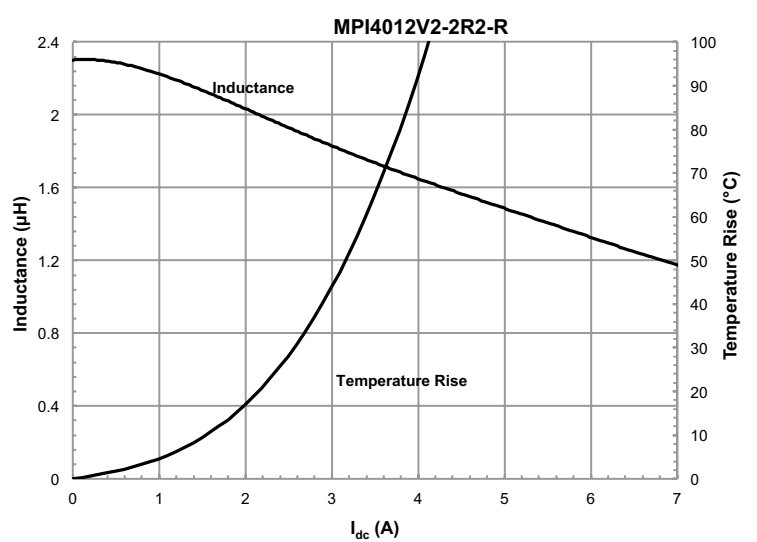
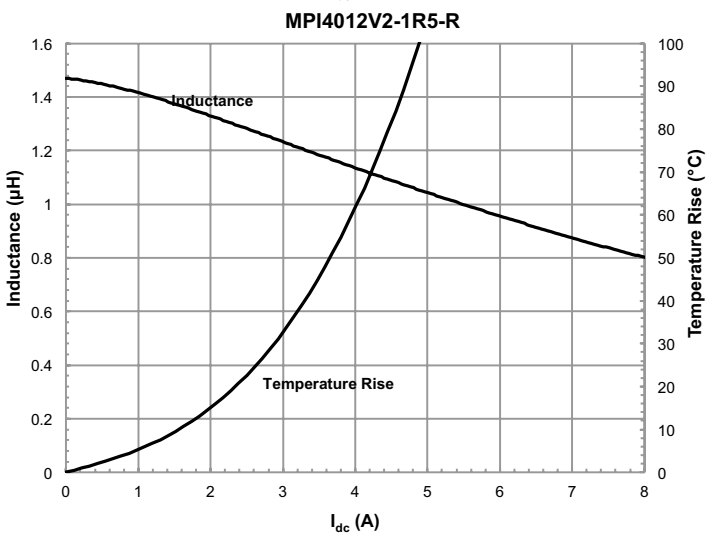
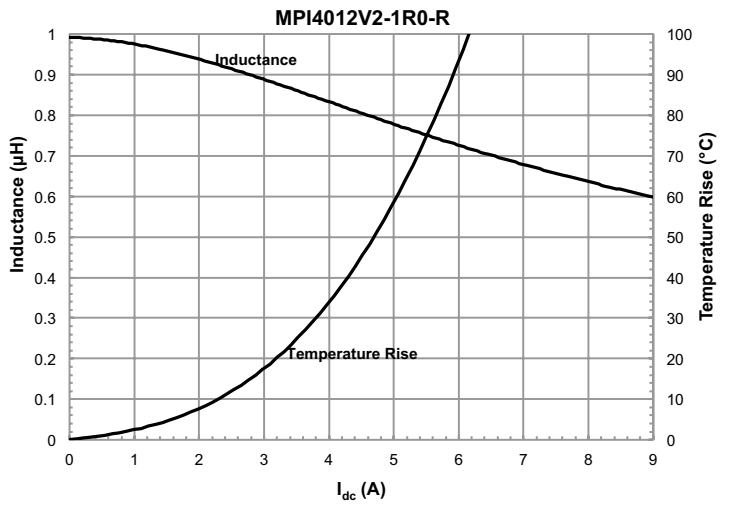
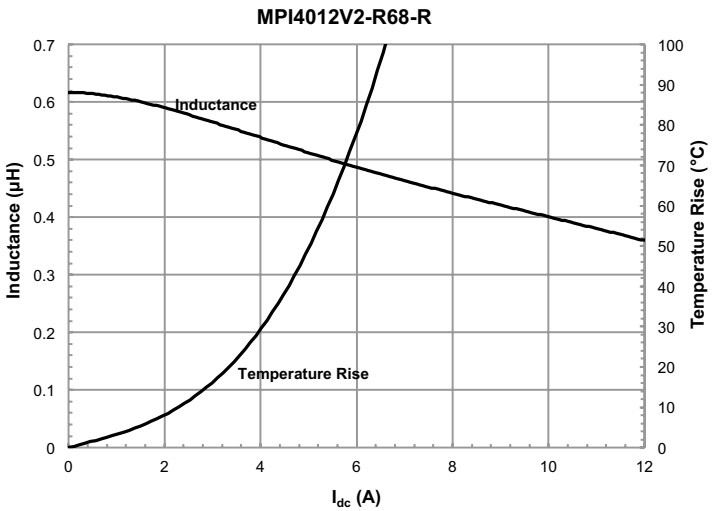
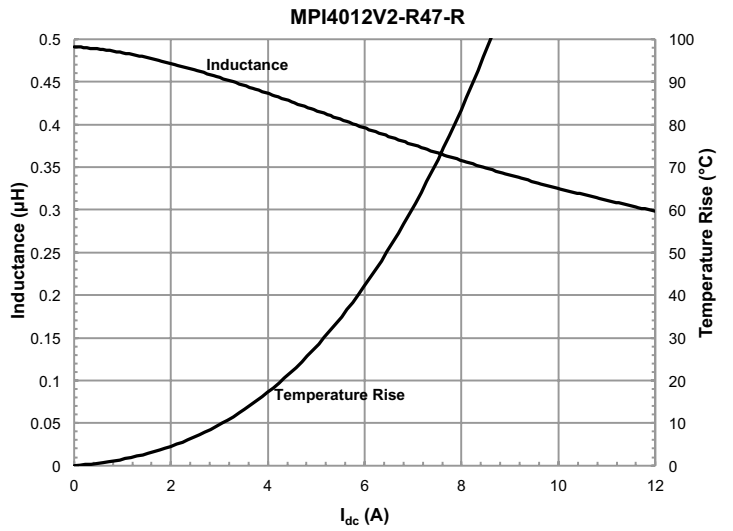
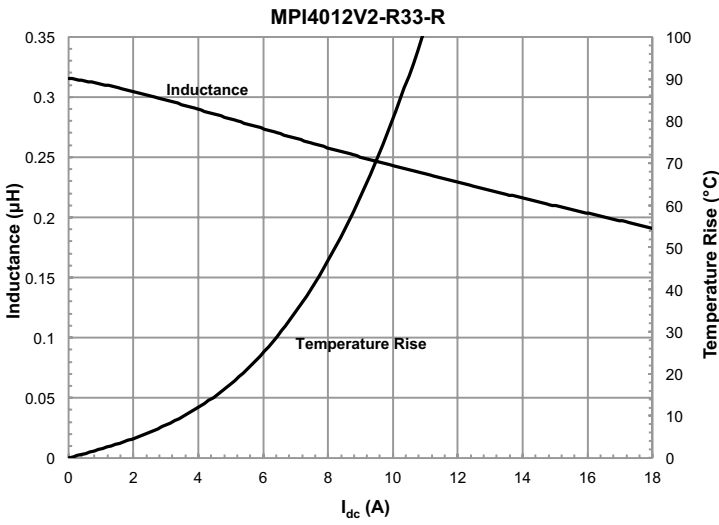
Inductance vs. Frequency



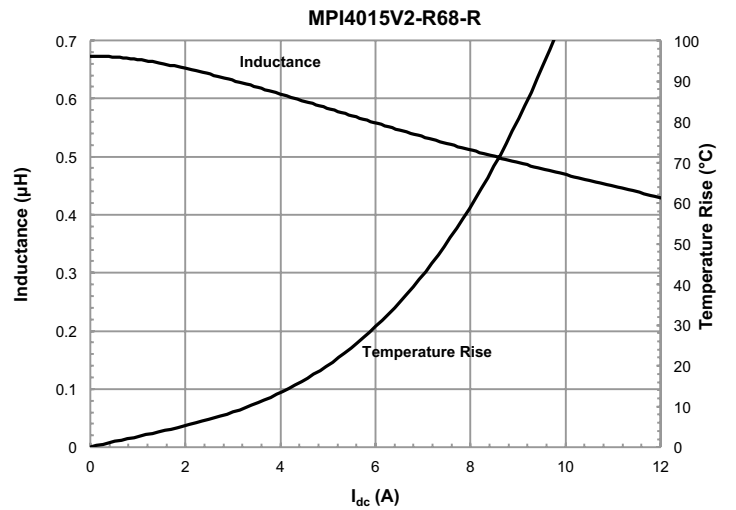
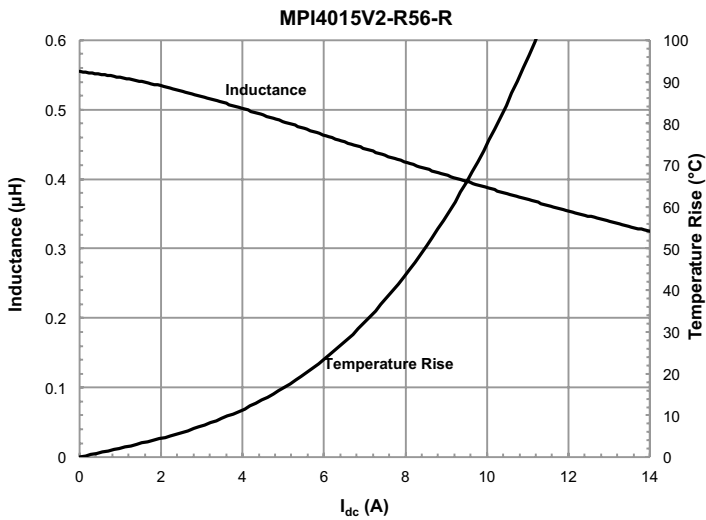
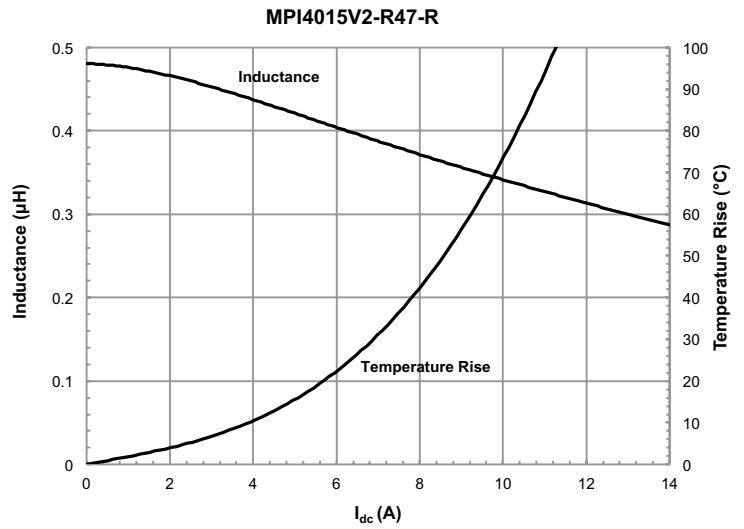
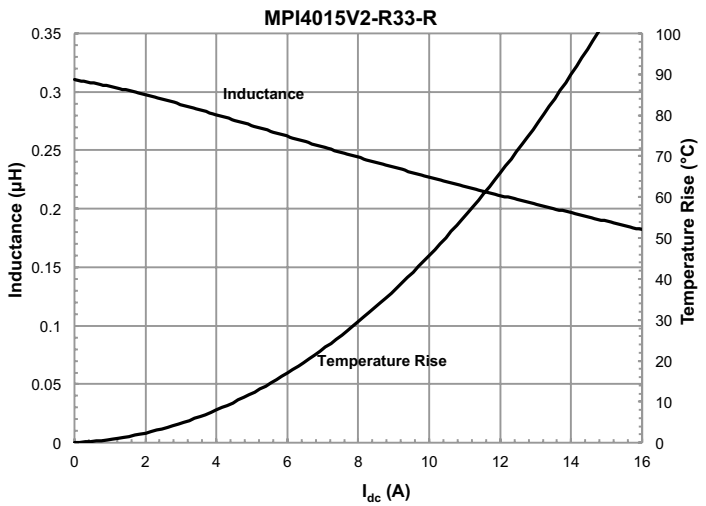
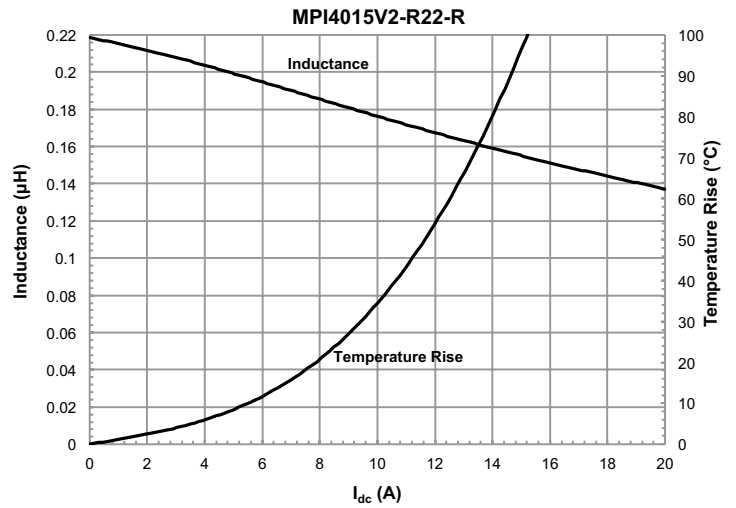
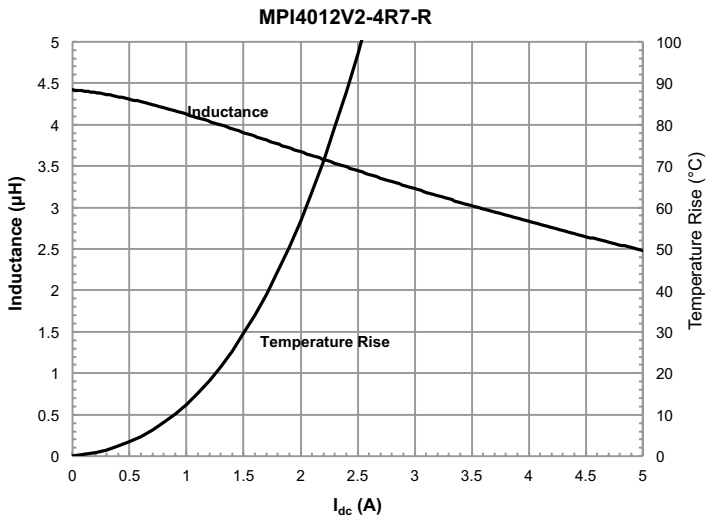
Inductance vs. Frequency



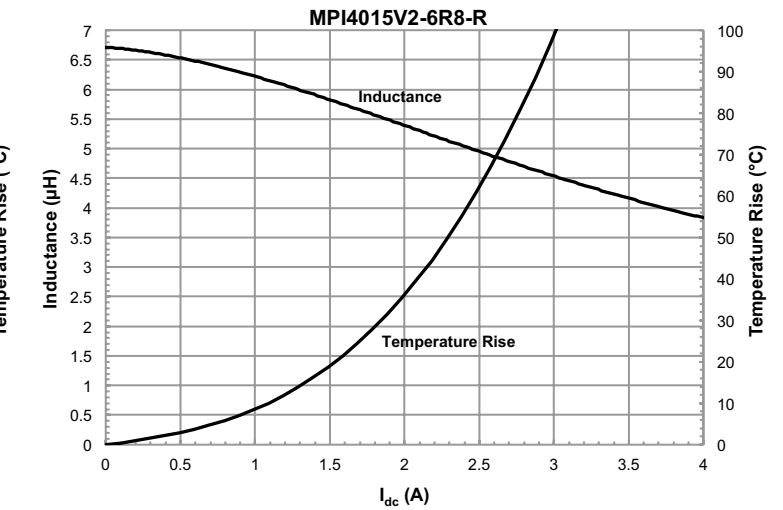
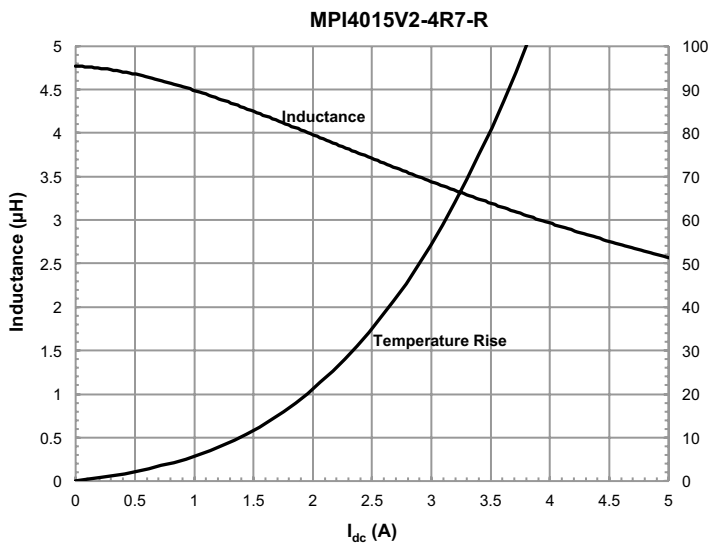
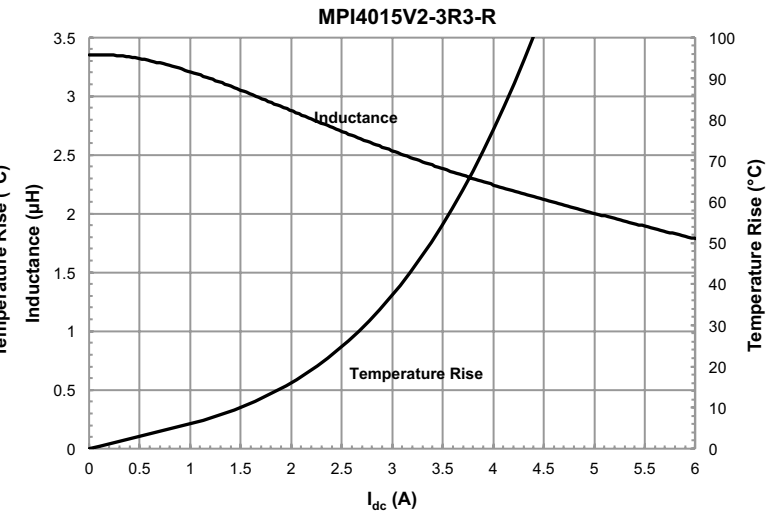
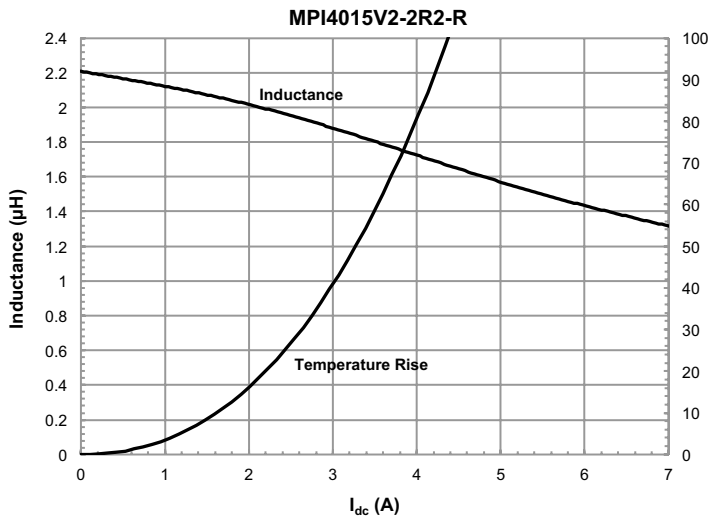
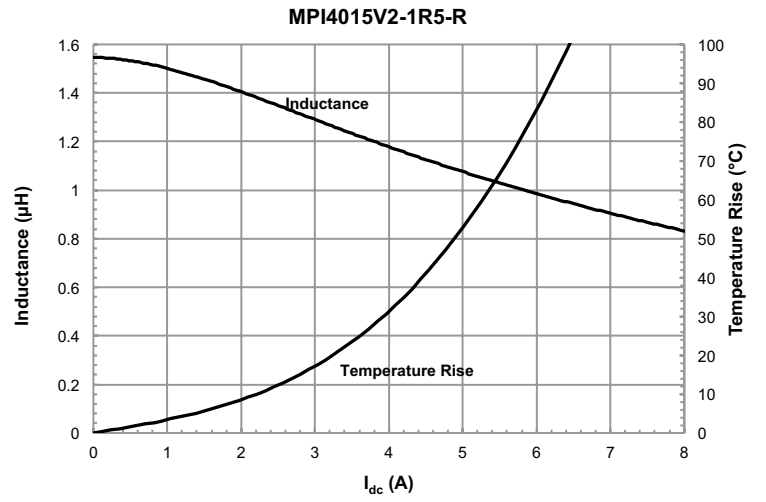
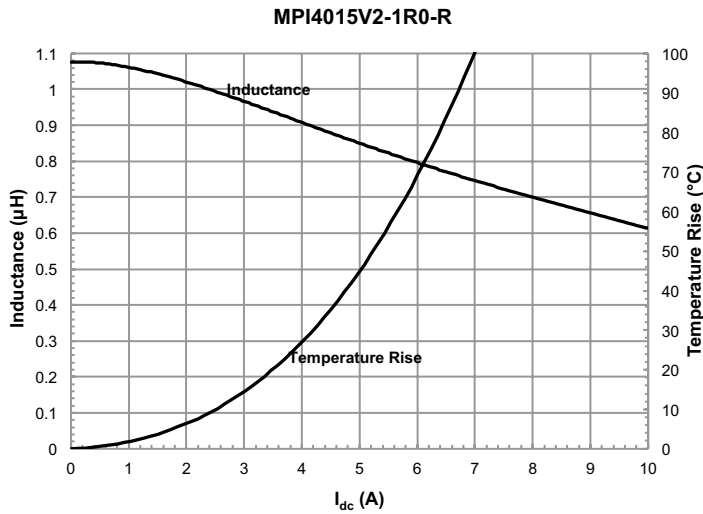
Inductance and temperature rise vs. Current



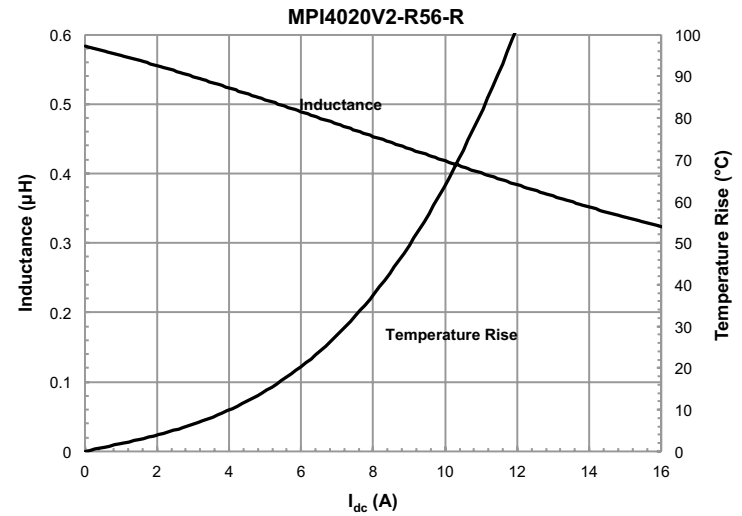
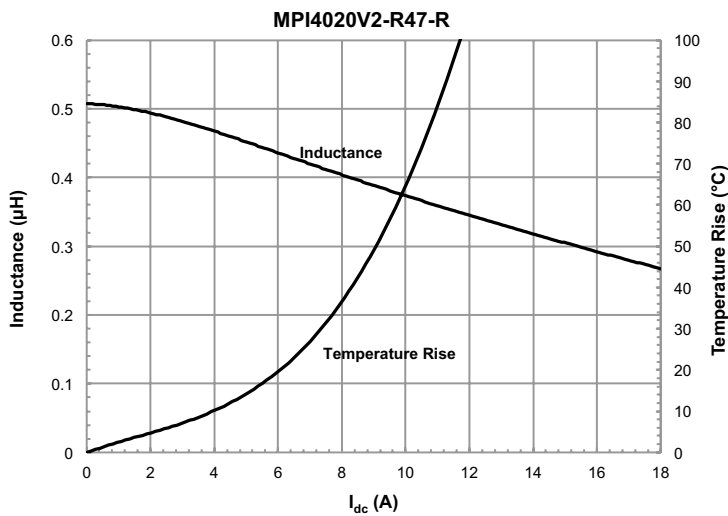
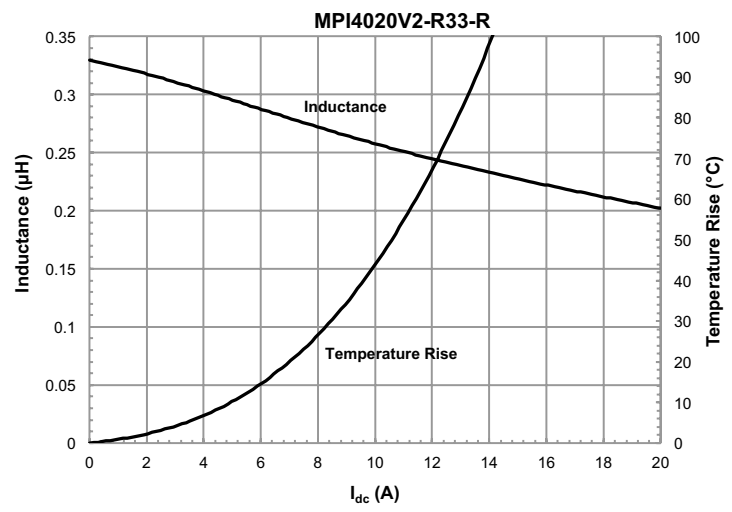
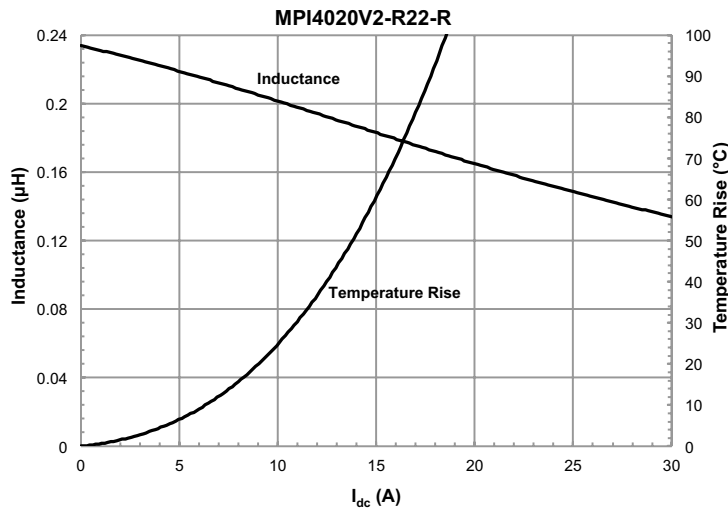
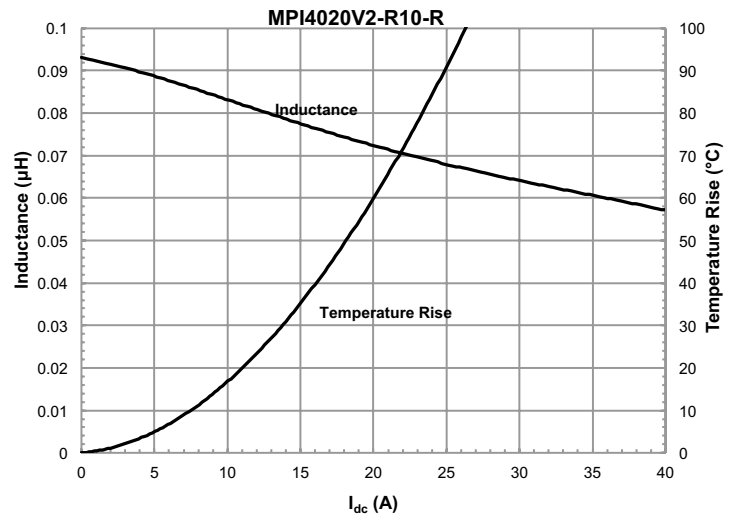
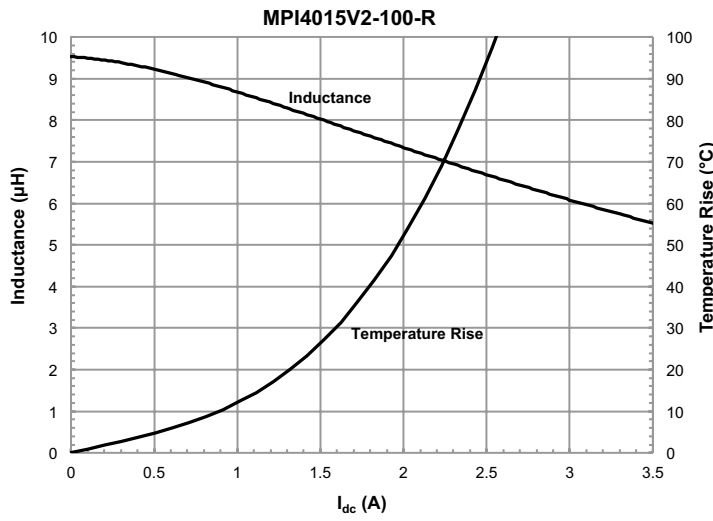
Inductance and temperature rise vs. Current



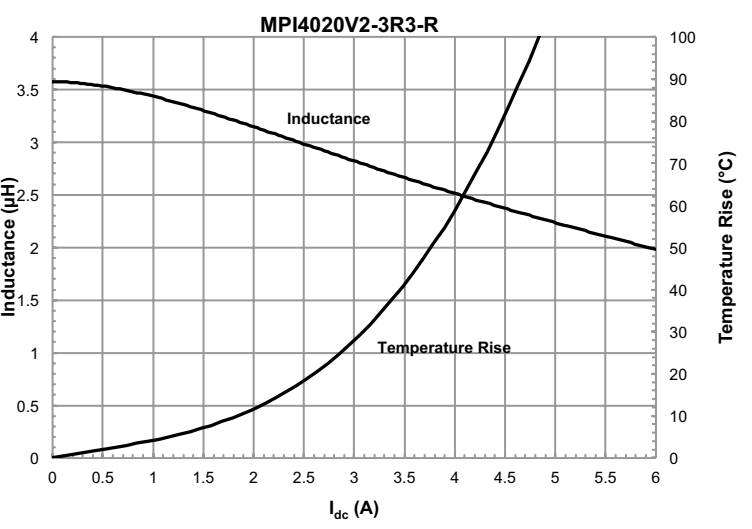
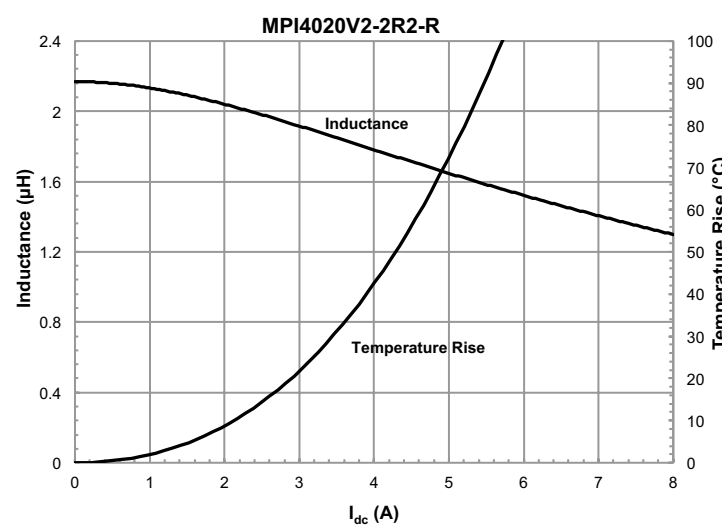
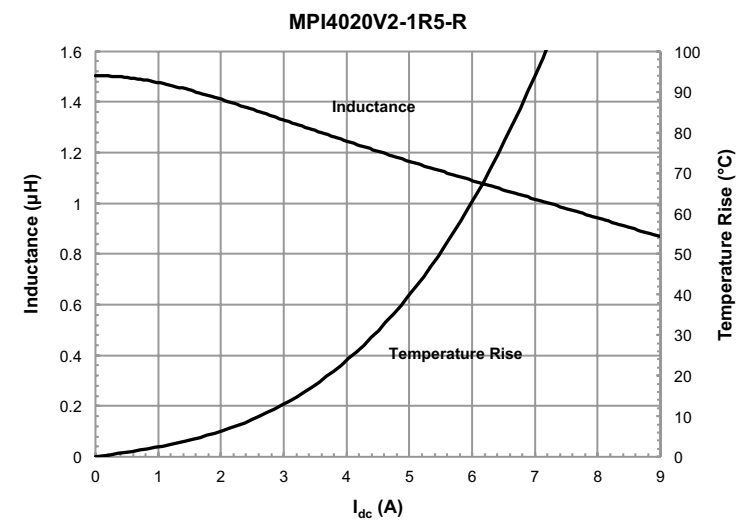
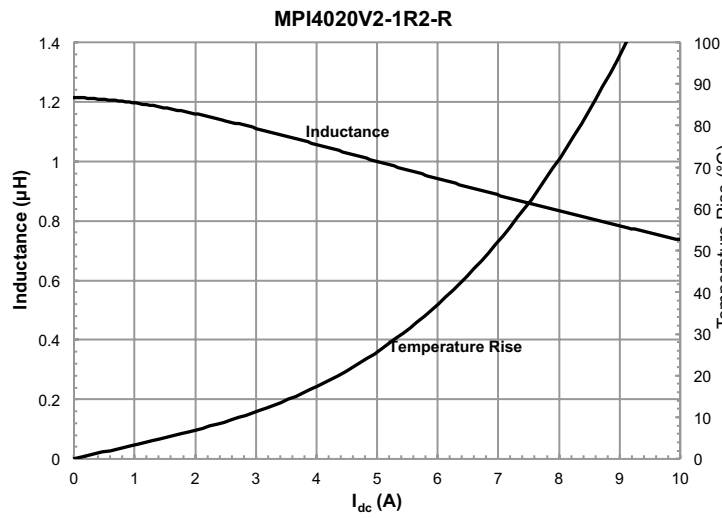
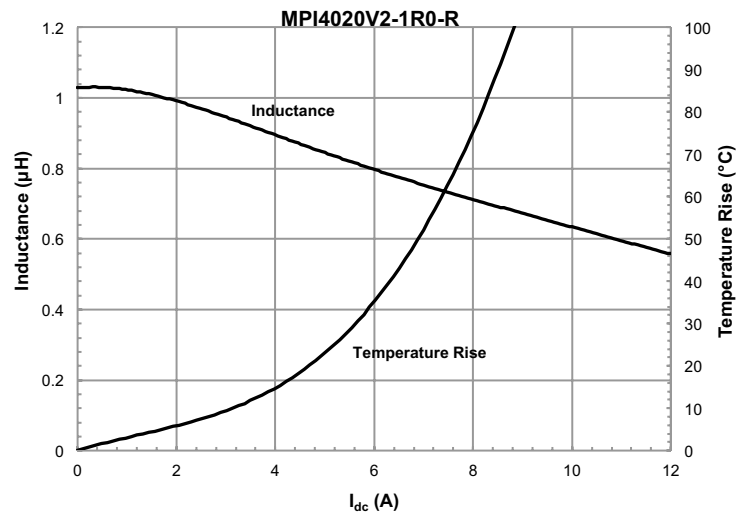
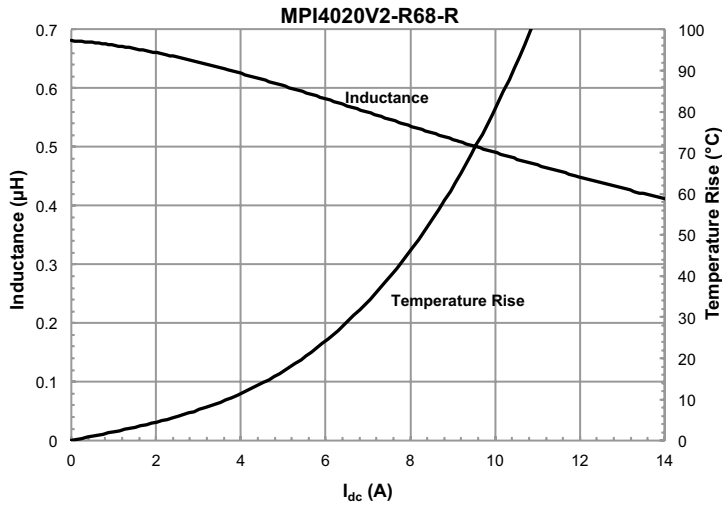
Inductance and temperature rise vs. Current



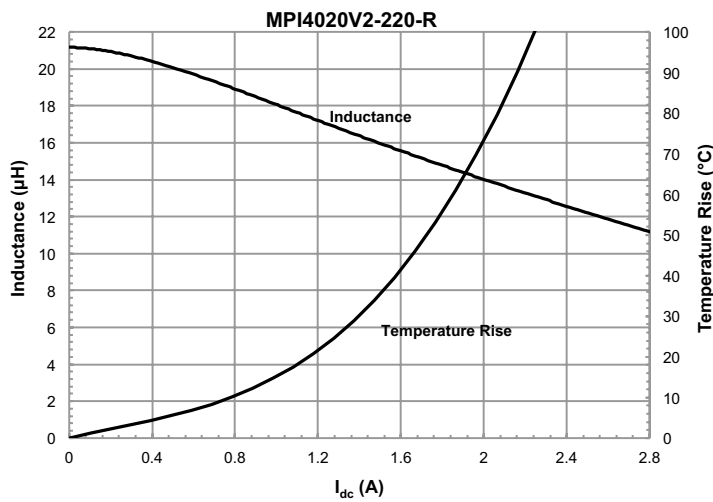
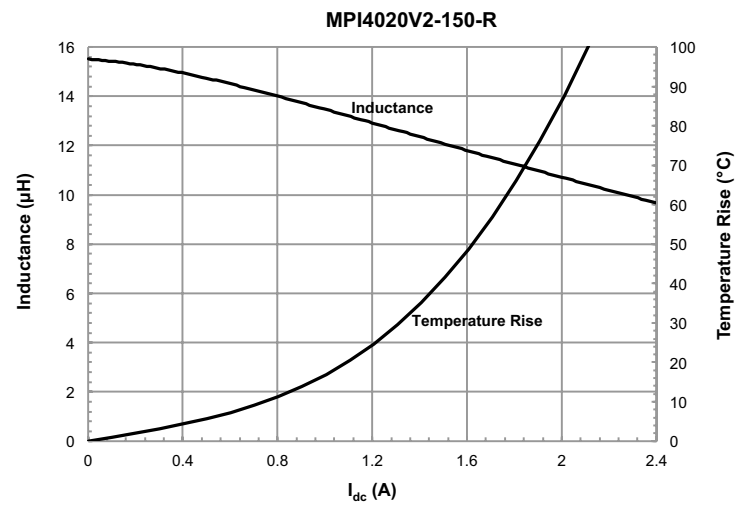
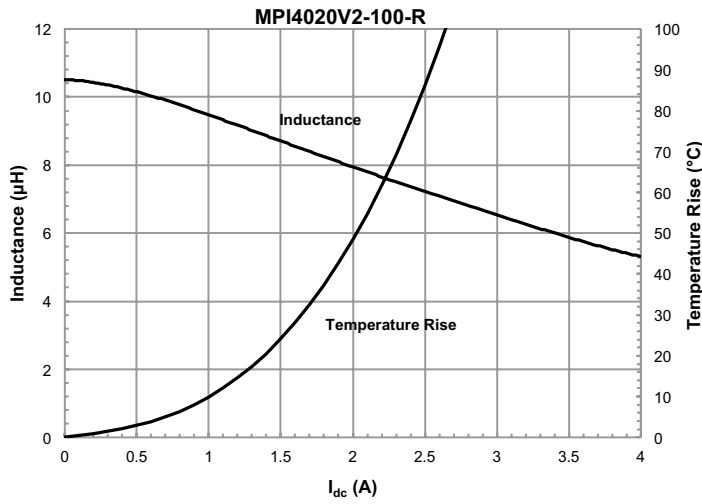
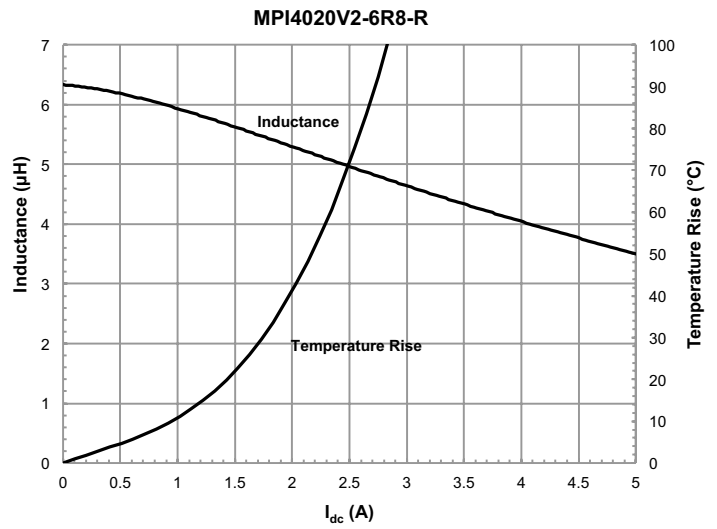
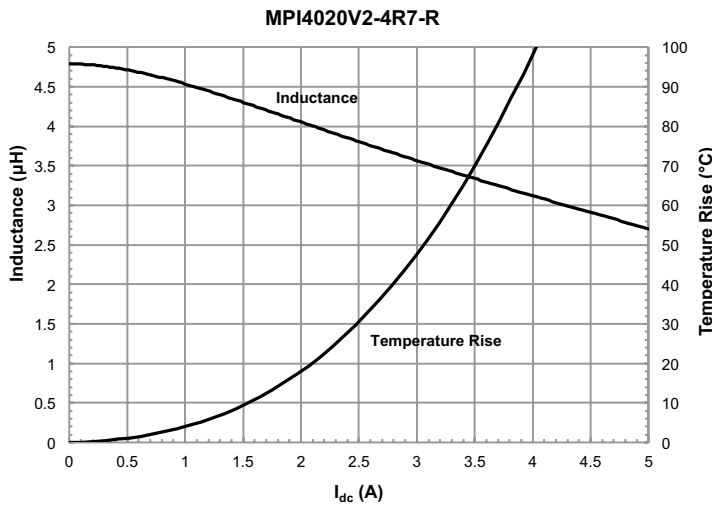
Inductance and temperature rise vs. Current



Inductance and temperature rise vs. Current



Inductance and temperature rise vs. Current



Solder reflow profile

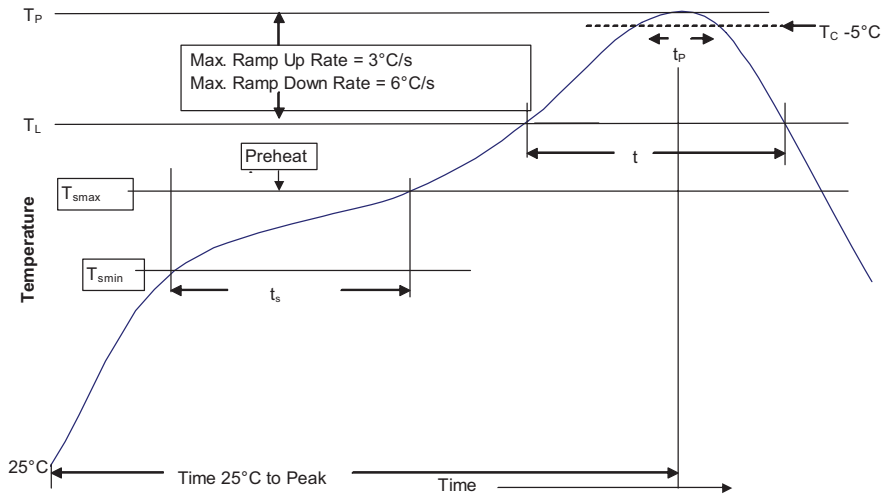


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5mm)	235 °C	220 °C
≥2.5mm	220 °C	220 °C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6mm	260 °C	260 °C	260 °C
1.6 – 2.5mm	260 °C	250 °C	245 °C
>2.5mm	250 °C	245 °C	245 °C

Reference JDEC J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T _{smin})	100 °C	150 °C
• Temperature max. (T _{smax})	150 °C	200 °C
• Time (T _{smin} to T _{smax}) (t _s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T _{smax} to T _p	3 °C/ Second Max.	3 °C/ Second Max.
Liquidous temperature (T _L)	183 °C	217 °C
Time at liquidous (t _L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T _p)*	Table 1	Table 2
Time (t _p)** within 5 °C of the specified classification temperature (T _C)	20 Seconds**	30 Seconds**
Average ramp-down rate (T _p to T _{smax})	6 °C/ Second Max.	6 °C/ Second Max.
Time 25 °C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.
 ** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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Eaton
Electronics Division
 1000 Eaton Boulevard
 Cleveland, OH 44122
 United States
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 Publication 10651 BU-MC17023
 April 2017

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